

An Introduction to the MC68HC16Z1

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1 Introduction

Use of microcontrollers (MCUs) presents new challenges as clock speeds increase and bus structures become more complex. In particular, designing a system with Freescale's 16-bit MC68HC16Z1 can be challenging for those used to the 8-bit world.

The MC68HC16Z1 is a member of the Freescale modular microcontroller family, a series of 16-bit and 32-bit devices constructed from standard on-chip peripheral modules that communicate by means of a standard intermodule bus. The MC68HC16Z1 is a sophisticated single-chip control system that incorporates a 16-bit CPU module (CPU16), a system integration module (SIM), a general-purpose timer (GPT), a queued serial module (QSM), an 8-channel analog-to-digital converter (ADC), and a 1-Kbyte standby RAM (SRAM). The MCU thus provides a designer with many options, ranging from reset configuration to interrupt generation, that must be considered during the design phase.

This tutorial is intended to assist development and reduce debug time for first-time designers of MC68HC16Z1 systems. It covers four major topics: designing the hardware, establishing communication, initializing the MCU, and troubleshooting. Each topic is discussed in a separate section that includes practical examples.

Along with two other Freescale documents *An Introduction to the HC16 for HC11 Users* (AN461) and *Transporting M68HC11 Code to M68HC16 Devices* (M68HC16PN01/D), this tutorial provides a "hands-on" supplement to the *MC68HC16Z1 User's Manual*, which presents a comprehensive overview of the MCU. For more information on device operation, electrical characteristics, registers, and control bit definition, refer to the appropriate sections of the manual. For more detailed information, refer to the reference manual for each of the on-chip peripheral modules. See **6 Sources of Information** for a complete list of MC68HC16Z1 technical literature.

The software examples included in the tutorial, and a sample system schematic, are available through Freeware Data Systems. The files are in the mcu16 directory in an archived file called "16Z1init.arc." The PKXARC utility is used to de-archive these files. PKXARC itself is contained in a self-expanding file entitled PKX35A35.exe, located in the Freeware IBM directory. Also in the mcu16 directory are "quikst20.arc" and "5band_sa.exe". The first file is an archive of several example/initialization files and the second is an archive of files to make a five-band frequency analyzer. See **6.2 Freeware Data Systems** for a phone number for modem access and addresses for internet access.

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2 Designing the Hardware

2.1 Using Data Bus Pins to Configure the MCU

The logic level of the data bus pins during reset determines many important operating characteristics of the MCU. Ensuring that the data bus is in a known condition during reset is vital to proper operation because the state of each data bus pin is sampled on the rising edge of the $\overline{\text{RESET}}$ signal. The data bus pins have weak internal pull-up circuitry that should cause them to default to a logic one if left floating (the pull-up current is 15 to 120 μA). However, since it is possible for external bus loading to overcome these internal pull-ups, it is a good idea to drive data bus pins that are critical to successful operation of the application to a known condition during reset and for at least 5 ns afterwards (there is a 5 ns hold time requirement after the release of $\overline{\text{RESET}}$ for a data bus pin to be recognized at a particular logic level). **Table 1** shows how each data bus pin affects the system configuration.

Table 1 Reset Mode Selection

Mode Select Pin	Default Function (Pin Left High)	Alternate Function (Pin Pulled Low)
DATA0	$\overline{\text{CSBOOT}}$ is 16-Bit Port	$\overline{\text{CSBOOT}}$ is 8-Bit Port
DATA1	$\overline{\text{CS0}}$ $\overline{\text{CS1}}$ $\overline{\text{CS2}}$	$\overline{\text{BR}}$ $\overline{\text{BG}}$ $\overline{\text{BGACK}}$
DATA2	$\overline{\text{CS3}}$ $\overline{\text{CS4}}$ $\overline{\text{CS5}}$	FC0 FC1 FC2
DATA3 DATA4 DATA5 DATA6 DATA7	$\overline{\text{CS6}}$ $\overline{\text{CS[7:6]}}$ $\overline{\text{CS[8:6]}}$ $\overline{\text{CS[9:6]}}$ $\overline{\text{CS[10:6]}}$	ADDR19 ADDR[20:19] ADDR[21:19] ADDR[22:19] ADDR[23:19]
DATA8	$\overline{\text{DSACK0}}$, $\overline{\text{DSACK1}}$, $\overline{\text{AVEC}}$, $\overline{\text{DS}}$, $\overline{\text{AS}}$, $\overline{\text{SIZE}}$	PORTE I/O pins
DATA9	$\overline{\text{IRQ[7:1]}}$, $\overline{\text{MODCLK}}$	PORTF I/O pins
DATA11	Slave Mode Disabled ¹	Slave Mode Enabled ¹
MODCLK	VCO = System Clock	EXTAL = System Clock
BKPT	Background Mode Disabled	Background Mode Enabled

Notes:

1. Slave mode is not a supported mode; it is used for factory testing. The slave mode must not be used in a customer application.

As an example, **Table 1** shows that the state of data bus pin 0 (DATA0) during reset determines whether $\overline{\text{CSBOOT}}$ operates as a 16-bit chip-select or as an 8-bit chip-select. Likewise, data bus pin 1 (DATA1) determines whether the $\overline{\text{CS0/BR}}$, $\overline{\text{CS1/BG}}$, and $\overline{\text{CS2/BGACK}}$ pins function as chip-select lines or as bus control signals. After reset, software can make other selections for these pins by writing to the appropriate pin assignment register.

A simple method of pulling a data bus pin high is to connect a 10 K Ω resistor between it and the 5 volt supply. Although putting a resistor on a data bus pin degrades performance at higher frequencies, many designers use resistive pull-ups without significant side effects. The preferred method of driving data bus pins during reset is by means of an active driver. A circuit to perform this function is shown in **Figure 1**. This circuit uses a 3-state buffer, such as a 74HC244 non-inverting octal driver, and meets the 5 ns hold time requirement. While this method does require external circuitry, it is recommended when high levels of noise may be encountered or when high reliability of operation is an overriding concern.

Tie 74HC244 inputs high or low, respectively, so that the desired logical values will be driven to the individual data bus pins when the output enable ($\overline{\text{OE}}$) pin is driven low. The $\overline{\text{OE}}$ will be driven low when the following three conditions are met: $\overline{\text{RESET}}$ is low, data strobe ($\overline{\text{DS}}$) is high, and read/write ($\overline{\text{R/W}}$) is

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high. Conditioning $\overline{\text{RESET}}$ with $\overline{\text{R/W}}$ and $\overline{\text{DS}}$ ensures that writes to external memory will be completed before the 74HC244s are enabled. Otherwise, if an external $\overline{\text{RESET}}$ signal was applied during a write to external memory and was not conditioned with $\overline{\text{R/W}}$ and $\overline{\text{DS}}$, the 74HC244s would turn on during the write and cause data bus contention.

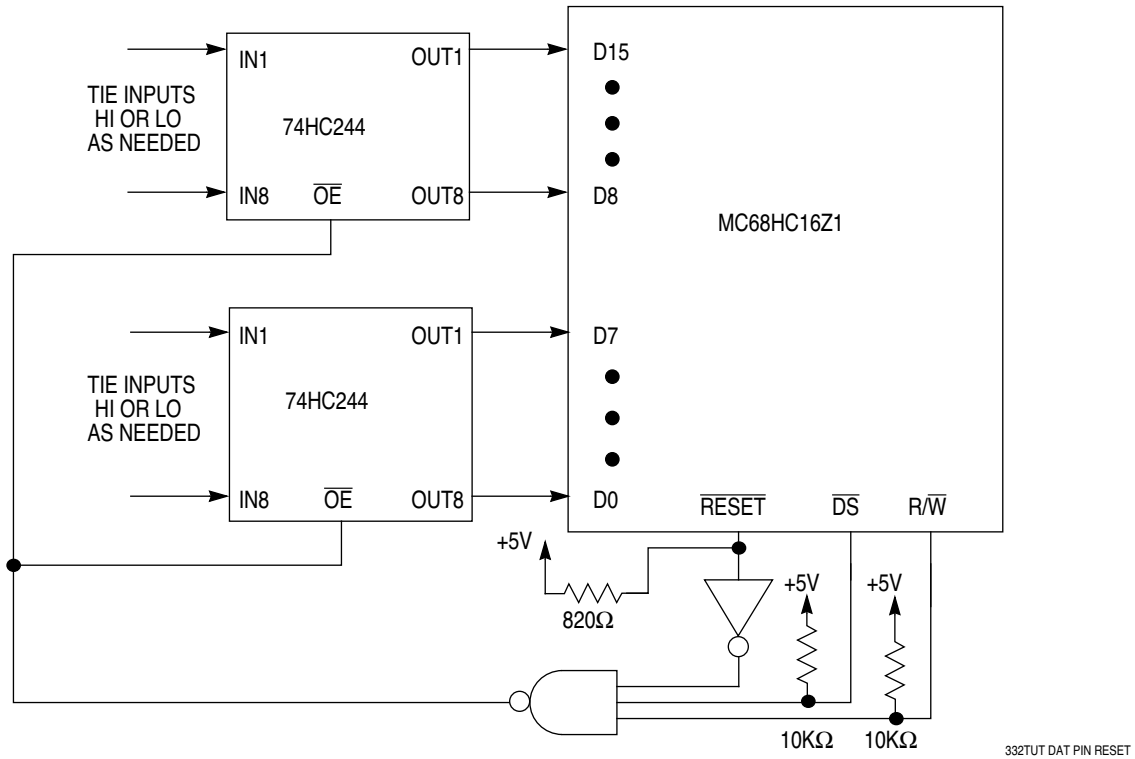


Figure 1 Circuitry to Drive Data Bus Pins During $\overline{\text{RESET}}$ Assertion

There are several alternative methods of driving data bus pins low during reset. The easiest methods are to connect a resistor in series with a diode from the data bus pin to the $\overline{\text{RESET}}$ line or to connect a transistor, as shown in **Figure 2**. When using a bipolar transistor, a base current limiting resistor is required. When using field effect transistor, a base limiting resistor is not needed. However, the best method is to use the configuration shown in **Figure 1**.

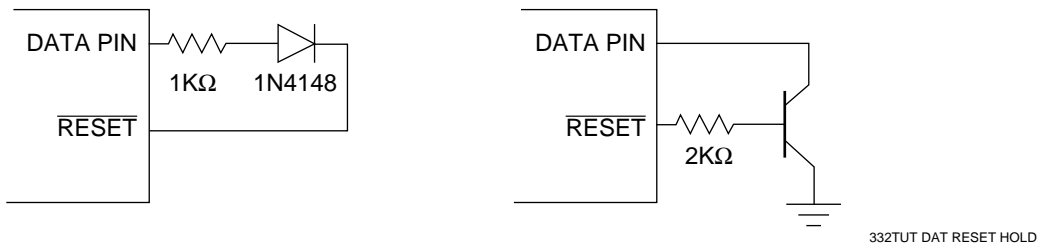


Figure 2 Alternate Methods of Conditioning Data Bus Pins

2.2 Choosing Memory Width

One decision that must be made early in the design is the width of memory to be used. Systems with 8-bit wide memory, 16-bit wide memory or a combination of the two can be implemented using only the

onboard chip-select lines.

Using 8-bit memory simplifies the design and reduces cost, but with a significant performance penalty. This penalty is not fixed, but depends on the amount of time that the processor spends accessing the 8-bit memory as opposed to accessing other external memory or performing internal accesses or operations. Moving from 16-bit to 8-bit program memory may reduce CPU performance by 40% when executing simple CPU instructions that only take a few clock cycles to execute. The impact is less in systems that make intensive use of CPU registers and complex instructions.

As a general guide:

- Use fast/word memory for the CPU stack, especially when programming in high level languages.
- Use fast/word memory for frequently accessed variables.
- Use fast/word memory for time critical routines, perhaps by copying them from slow main ROM into fast external or internal RAM.
- Use slow/byte memory for rarely executed, non-critical routines, such as initialization routines.

2.3 Pins that Need Pull-Up Resistors

Many of the input pins need pull-up resistors to prevent unexpected conditions. The pins discussed below must be conditioned in all applications. An incorrect voltage on one or more of them can cause general system failure. Other input pins, such as TPU inputs, can be left floating without adverse effect in certain applications. The designer must determine which pins can cause system failure in a particular application and deal with them appropriately. In general, it is best to condition all input pins so that they are in a known state, whether they are used or not.

Never connect a pin directly to 5 volts if it is possible to configure the pin as an output. Attempting to drive an output low when it is connected to voltage source can damage the output drivers. Many of the pins have dual functions and can be configured as I/O pins by holding specific data bus lines low during reset. When a pin is configured for I/O during reset and will never be reconfigured for the alternate function, a pull-up resistor may not be needed. **Table 1** shows which signals are affected by data bus pin state during reset.

$\overline{BR/CS0}$ — Use a 10 K Ω pull-up to prevent an unexpected bus request. This pin is configured as a chip-select pin when DATA1 is held high at the release of reset. Conditioning DATA1 as described in **2.1 Using Data Bus Pins to Configure the MCU** precludes use of a pull-up.

\overline{BERR} — This is an input signal that is asserted in the absence of \overline{DSACK} to indicate a bus error condition. Using a 10 K Ω pull-up resistor prevents the unexpected assertion of bus error.

\overline{HALT} — This is an active-low bidirectional signal that can be used to halt the external bus, among other things. Using a 10 K Ω pull-up resistor will prevent an erroneous bus halt. Since \overline{HALT} is a bidirectional signal, do not connect it directly to \overline{BERR} , \overline{RESET} or 5 Volts.

$\overline{IRQ[7:1]}$ — Although the interrupt lines have internal pull-up circuitry, the circuitry is weak and can be overcome by noise and capacitive coupling. Make certain that pins configured for use as interrupt-request inputs rather than for use as general-purpose I/O are pulled up to 5 Volts.

There are two ways to lessen the chances for erroneous interrupt service requests:

1. Hold DATA9 low during reset as described in **2.1 Using Data Bus Pins to Configure the MCU** to assign all these pins to general-purpose I/O port F. Pull up lines that are to be used for interrupt service to 5 V via 10 K Ω resistors, hold DATA9 low during reset, reassign the pins to be used for interrupt requests by writing to the port F pin assignment register, then change the IPL mask value to enable maskable interrupts.

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2. Hold DATA9 high during reset as described in **2.1 Using Data Bus Pins to Configure the MCU** to assign all these pins for use as interrupt-request inputs. Pull up all lines that are to be used for interrupt service, including $\overline{\text{IRQ7}}$, to 5 V via 10 K Ω resistors, hold DATA9 high during reset, re-assign the pins that are not used for interrupt requests by writing to the port F pin assignment register, then change the IPL mask value to enable maskable interrupts.

Remember that the level 7 interrupt is non-maskable — when configured as an interrupt line, $\overline{\text{IRQ7}}$ is always enabled. The only way to disable external $\overline{\text{IRQ7}}$ interrupts is to assign the $\overline{\text{IRQ7}}$ pin to I/O function via the port F pin assignment register.

DSACK[0:1] — During bus transfers, external devices can drive these signals to indicate port width. These signals are active even if the bus transfer is to or from a peripheral that is using one of the chip-selects to terminate the bus cycle. Putting 10 K Ω pull-ups on these two pins prevents accidental assertion of DSACK[0:1], which can occur if the pins are left floating.

AVEC — If this signal is asserted during an interrupt acknowledge cycle, an autovector will be used for the external interrupt being serviced. If the AVEC pin is connected permanently to ground, all external interrupts will autovector. Using a 10 K Ω pull-up resistor will prevent unexpected assertion of the AVEC pin.

TSTME/TSC — The inactive state of this pin is 5 Volts. Pulling it low enables special test mode, but the MCU cannot enter test mode unless the state of a bit in one of the test mode registers is changed by the software. Although this should happen only if the software is corrupted, to prevent entering special test mode, put a 10 K Ω pull-up resistor on this pin. Special test mode is generally used only for factory testing. Driving this pin to approximately 1.6 times V_{DD} causes the MCU to place all output drivers in a high-impedance state, isolating the MCU from the rest of the system.

BKPT/DSCLK — Background debug mode (BDM) operation is enabled when $\overline{\text{BKPT}}$ is asserted at the rising edge of the $\overline{\text{RESET}}$ signal. BDM remains enabled until the next system reset. If $\overline{\text{BKPT}}$ is at a logic level one on the trailing edge of $\overline{\text{RESET}}$, BDM is disabled. $\overline{\text{BKPT}}$ is re-latched on each rising transition of $\overline{\text{RESET}}$. A 4.7 K Ω pull-up resistor will ensure that BDM is not unexpectedly enabled upon reset.

R/W — Putting a 10 K Ω pull-up resistor on this pin will prevent accidental writes to memory while the device is being powered up. Normally, R/W is always defined. However, when power is first applied to the device, R/W can be undefined for a few cycles. This may cause a problem for EEPROM or battery backed up RAM.

RESET — An 820 Ω pull-up resistor is required for this pin. Do not put capacitors on the $\overline{\text{RESET}}$ pin. The reason for such a strong pull-up and no extra capacitance is that the $\overline{\text{RESET}}$ line must rise to a logic 1 within approximately 10 system clocks after the MCU has driven $\overline{\text{RESET}}$ low for 512 clocks, or else the MCU re-asserts the $\overline{\text{RESET}}$ line for an additional 512 clock cycles.

MODCLK — If using the internal PLL to generate the system clock, this pin must be pulled up with a 10 K Ω resistor or driven high during reset. If using an external clock source and bypassing the PLL, connect this pin to ground or drive it low during reset.

2.4 Using Sockets

Because of the high pin count the MCU package has a very narrow lead pitch, which makes it nearly impossible to hand-solder onto a board. This is not a problem for design activities that can manufacture PC boards, but designers who are assembling a limited number of prototypes or who cannot manufacture PC boards will probably need to use a socket to hold the chip. The wider spacing of socket pins makes it possible to connect the socket to a board.

Sockets are not a place to economize. Use a good quality socket that firmly holds the MCU in place so that all pins maintain contact. If the MCU is likely to be removed and replaced, consider using a zero insertion force socket.

Three socket manufacturers are:

2.5 Clock Circuitry

The designer must decide whether to use the internal frequency synthesizer circuit or an external clock to produce the system clock signal. Both options are discussed in the following paragraphs.

2.5.1 Using the Internal Frequency Synthesizer Circuit

The MCU uses a voltage-controlled oscillator (VCO) and a phase-locked loop (PLL) to generate an internal high speed clock. This arrangement permits low power operation using only the low frequency oscillator. Low frequency in CMOS technology translates into low power because power consumption is proportional to frequency.

The internal frequency synthesizer circuit is enabled when the MODCLK pin is pulled high during reset. The synthesizer requires a reference frequency in order to operate. There are two reference frequency options: a crystal oscillator circuit or an external clock reference, such as a canned oscillator circuit (a single package which contains the crystal and buffer circuit) as the input.

2.5.2 Using a Crystal Oscillator Circuit

2.5.2.1 Oscillator Components

The crystal oscillator used is a Pierce oscillator, also known as a parallel resonant crystal oscillator. It is shown in **Figure 3**. Its components consist of a series resistor, a feedback resistor, a crystal, an inverter, and two capacitors:

Rs — Series resistor R_s must be large enough to appropriately limit current to the crystal and yet small enough to provide enough current to start oscillation quickly. The smaller R_s , the faster the oscillator will start. However, if R_s is too small, the crystal will start up in unpredictable modes or dissipate too much power. This can cause heating problems. In extreme cases, the crystal may even be damaged and not work properly again. If R_s is too large, the oscillator will start very slowly or not at all. The best way to minimize start-up time is to minimize the size of R_s within the guidelines of the maximum power dissipation.

The crystal manufacturer generally recommends a range of values to use. To ensure that R_s is large enough to prevent the crystal from being overdriven, observe the output frequency as a function of V_{DD} on the CLKOUT pin. If the crystal is overdriven at start-up, i.e., the first 500 ms or so after the power is turned on, the frequency will be very unstable.

Rf — Feedback resistor R_f is used to bias the inverter between EXTAL and XTAL inside the MCU. R_f affects the loop gain; lower values reduce gain, while higher values increase gain.

C1 and C2 — The series combination of C1 and C2 provides the parallel load for the crystal. Their values may be varied to trim frequency. In high frequency applications, C1 and C2 are usually equal. However, in low frequency applications, C1 can be smaller than C2 (about 5 pF) to provide a higher voltage at the EXTAL input. A wider voltage swing at this input will result in lower power-supply current. Usually, the actual capacitances will be smaller than the intended capacitances since circuit and layout capacitances add to the values of C1 and C2.

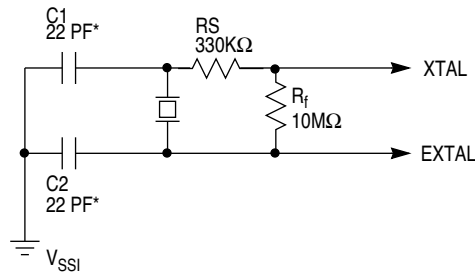
Inverter — The inverter is inside the MCU. It provides the 180 degree phase shift necessary for oscillation.

Crystal — The crystal is made of piezoelectric quartz. It must be a good quality crystal that is capable of suppressing harmonics and overtones and quickly locking onto the fundamental frequency. If a particular crystal type or brand is prone to starting with overtones or harmonics, don't use it. No amount of circuit design can compensate for a bad or poor quality crystal.

The MCU is designed to use a 32.768 kHz AT-cut crystal to produce an 8.389 MHz CLKOUT signal. The frequency of the internal clock can be increased or decreased by writing to the SYNCR register.

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Figure 3 shows clock circuitry for a Daishinku DMX-38 32.768 kHz crystal, but the circuit will work for most other 32.768 kHz crystals also. To use other crystal values (the allowable range is 20 kHz – 50 kHz), consult the crystal vendor for analysis of the crystal components needed.



* RESISTANCE AND CAPACITANCE BASED ON A TEST CIRCUIT CONSTRUCTED WITH A DAISHINKU DMX-38 32.768-KHZ CRYSTAL. SPECIFIC COMPONENTS MUST BE BASED ON CRYSTAL TYPE. CONTACT CRYSTAL VENDOR FOR EXACT CIRCUIT.

332TUT XTAL CONN 1

Figure 3 System Clock with a 32.768 kHz Reference Crystal

For the most accurate oscillator frequency, use the Pierce version of the crystal (rather than the series resonant version) with C1 and C2 values to match the specified load capacitance of the crystal. As a side note, start-up time is inversely proportional to frequency. A 32 kHz crystal may take several hundred milliseconds to start up. Be aware: all crystals are not created equal nor are they close. In fact, there are several different types of tuning elements that can be used for low frequency oscillators in the range of 32.768 kHz. While there are many characteristics of the various tuning elements that can be precisely measured, there are other characteristics that are extremely difficult to measure and express in a useful way.

Maximum power dissipation of a crystal is generally specified by the manufacturer of the device. Crystal power dissipation is a function of the reactance of the combined input and output capacitance of the internal amplifier of the microcontroller and of the external circuit components including the crystal itself. The manufacturer specifies this value and also specifies a circuit, usually one like that of **Figure 3**, along with the circuit values. The crystal manufacturer makes a tacit assumption that the amplifier has enough drive capability to handle the required load, so that the output voltage levels of the amplifier are not affected.

Parameters related to suppression of harmonics and overtones are generally not specified by the crystal manufacturer. Harmonics are integer multiples of the fundamental frequency. The first overtone is approximately 1.7 times the fundamental frequency. Since a typical oscillator circuit forms a low pass filter, the 3 db roll-off point should be set at about 1.5 times the fundamental frequency of the crystal. This should cause no attenuation at the fundamental but should cause significant attenuation at the first overtone and even greater attenuation at the first harmonic. When figuring the reactance of the entire circuit, it is most important to use the typical parameters of the crystal, the input and output capacitance of the amplifier and the remainder of the external components in the calculation.

Many companies make crystals. Most re-sell their products through electronics distributors that are listed in the *EITD Electronic Industry Telephone Directory*. Refer to **6 Sources of Information** for ordering information.

Four crystal manufacturers are:

ECS — (800) 237-1041

The part number for a surface mount 32.768 kHz crystal with a temperature range of –40 to +85 degrees Celsius is ECX205. This crystal also comes in other packages.

Fox — (813) 693-0099

**For More Information On This Product,
Go to: www.freescale.com**

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The part number for a surface mount 32.768 kHz crystal with a temperature range of -40 to $+85$ degrees Celsius is FSM327. This crystal also comes in other packages.

KDS (Daishinku) — (913) 491-6825

The part number for a surface mount 32.768 kHz crystal with a temperature range of -40 to $+85$ degrees Celsius is DMX-38. This crystal comes in other packages.

Statek — (714) 639-7810

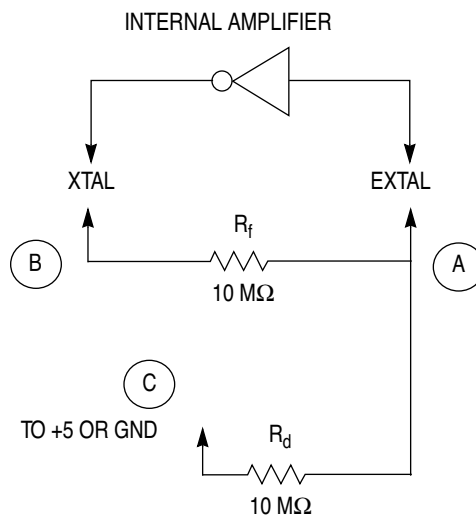
The part number for a surface mount 32.768 kHz crystal that can be used at 25 degrees Celsius is CX-1VS-SMI 32.768kHz. For a temperature range of -40 to 85 degrees Celsius, the part number is CX-1VS-SMI 32.768kHz A/I.

2.5.2.2 Grit and Grime

Oscillators are quite sensitive to dirt, solder flux, grease and other conducting materials on the circuit board. These materials can allow a very high resistance leakage path from one of the amplifier pins to either ground or the positive terminal of the power supply. When the oscillator has power applied but has not started, the crystal and bypass capacitors appear as DC open circuits. An oscillator in a DC condition would appear as shown in **Figure 4**.

The resistor, R_d , represents a high-resistance leakage path, somewhere in the range of 5 to 20 $M\Omega$. The feedback resistor, R_f , is also in this range. Assuming that R_d and R_f are both 10 $M\Omega$, the voltage at point A is half the voltage difference between points B and C. Thus, if the XTAL pin is at a logic 1 (4.5 volts) and point C is at ground, the voltage at point A (EXTAL pin) will be 2.25 volts. If point B is at a logic 0 (0.5 volts) and point C is at ground, the voltage at point A is 0.25 volts. Thus, the voltage at point A may be interpreted as a logic 0 regardless of whether the XTAL pin is a logic 1 or a logic 0. This depends on the threshold of the inverter whose input is connected to point A. Likewise, if point C is connected to 5 volts, point A may be interpreted as a logic 1 regardless of the state of the XTAL pin. A circuit with this problem will not oscillate.

The only way to diagnose this problem is to remove the external circuit components as well as the MCU from the board and use an Ohm meter to check the resistance from points A and B to ground. Anything other than a completely open circuit is a sign of trouble. The obvious solution is to clean the printed circuit board. If the dirt or grime that form the high resistance path is on an inner layer of the printed circuit board, the board is unusable.



332TUT XTAL RF/RD CONN

Figure 4 DC Model of Oscillator Circuit

2.5.2.3 Layout and Strange Behavior

Oscillator layout is just as important as a good quality crystal and cleanliness in manufacturing the printed circuit board. The best possible solution is to use a multi-layer board with a separate ground plane. The rules for oscillator layout are quite simple. First, locate the crystal and all associated external components as close to the oscillator pins as possible. Second, do not under any circumstance run a high-frequency trace under either the feedback or series resistor or the crystal. Third, if there is no separate ground plane, make sure that the ground for the bypass capacitors is connected to a solid ground trace. **Figure 5** shows typical one-layer oscillator layout.

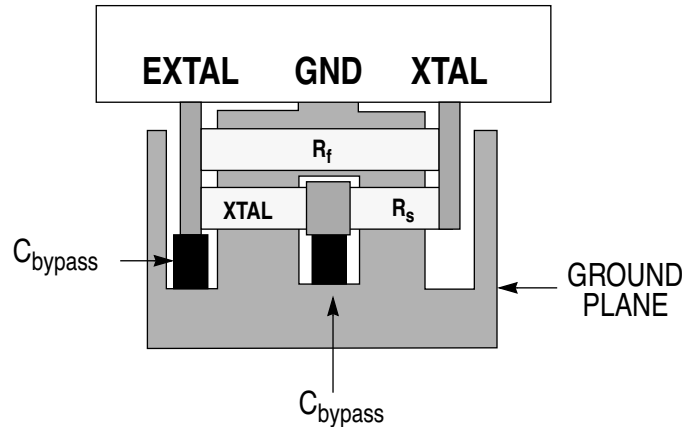


Figure 5 Typical One-Layer Oscillator Layout

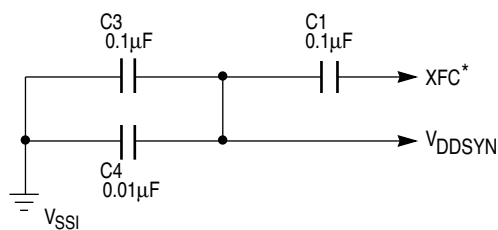
Do not run high frequency conductors near, and particularly underneath, the crystal, the feedback resistor or the series resistor. In **Figure 5**, only a ground trace runs underneath these components. Also note that, in **Figure 5**, the ground trace is tied to the ground pin nearest to the oscillator pins. This helps prevent large loop currents in the vicinity of the crystal. It is also very important to tie the ground pin to the most solid ground in the system. The trace that connects the oscillator and the ground plane should not connect to any other circuit element as the injection of current into this trace tends to make the oscillator unstable.

2.5.2.4 XFC and V_{DDSYN}

Noise on the XFC, V_{DDSYN} , and V_{SSI} pins causes frequency shifts in CLKOUT. The XFC filter capacitor and the V_{DDSYN} bypass capacitors should be kept as close to the XFC and V_{DDSYN} pins as possible with no digital logic coupling to either XFC or V_{DDSYN} . The ground for the V_{DDSYN} bypass capacitors should be tied directly to the V_{SSI} ground plane. If possible, route V_{DDSYN} and V_{SSI} as separate supply runs or planes. V_{DDSYN} may require an inductive or resistive filter to control supply noise.

A V_{DDSYN} resistive filter would consist of a 100 to 500 Ω resistor from V_{DD} to V_{DDSYN} and a 0.1- μ F bypass capacitor from V_{DDSYN} to V_{SSI} . The proper values for the resistor and capacitor can be determined by examining the frequency of the V_{DDSYN} noise. The RC time constant needs to be large enough to filter the supply noise. An inductive filter would replace the resistor with an inductor.

The low-pass filter requires an external low-leakage capacitor, typically 0.1 μ F with an insulation resistance specification as high as practical. The main criterion is that the capacitor be low-leakage because leakage affects frequency stability and accuracy. Do not use a tantalum capacitor. Although the *SIM Reference Manual* (SIMRM/AD) recommends an insulation resistance of 30,000 M Ω , this value may not be necessary in all applications. For most consumer (room temperature) applications, polystyrene capacitors are recommended. See **Figure 6** for a recommended circuit.



* MAINTAIN LOW LEAKAGE ON THE XFC NODE.

332TUT XFC CONN

Figure 6 Conditioning the XFC and V_{DDSYN} Pins

2.5.2.5 Evaluating Oscillator Performance

Once an entire oscillator circuit is built, it is very important to evaluate circuit characteristics. Of particular interest is how the oscillator starts. If the oscillator starts in a metastable state that persists for several hundred milliseconds, it is quite possible that this state will persist until the MCU releases reset and tries to start fetching instructions. When this happens, the PLL may well be operating at a frequency far greater than the maximum specified for the MCU. Any variation in the input frequency of the PLL is multiplied by the feedback ratio of the PLL. If the MCU starts operating, i.e., reset is released and the internal clocks are gated to the internal buses, while the oscillator is operating at an overtone or first harmonic, the MCU will probably enter an inoperative state in which it cannot be restarted by a hardware reset. In this case, the only option is to turn the system power off and then attempt a power-on reset.

Because oscillators are very sensitive circuits, malfunctions are difficult to diagnose by conventional means such as probing the input and output with an oscilloscope. The capacitance of a scope probe can be large compared to the effective capacitance of the particular node of the oscillator that is probed. This added capacitance can cause an errant oscillator to move to a more stable region where it appears to work correctly or, on the other hand, a working oscillator could be moved into a region of no oscillation at all. Therefore, it is important to measure oscillator performance indirectly. This can be done through the CLKOUT pin, which is a buffered form of the internal system clock. Monitoring the CLKOUT pin with an oscilloscope does not affect the oscillator and provides an accurate representation of oscillator problems. If the MCU is running off the internal PLL and a 32.768 kHz crystal, the CLKOUT frequency should be 8.389 MHz at the release of reset.

The CLKOUT signal is likely to do one of three things when power is turned on. It will either remain at a constant DC level, jump quickly to the proper frequency, or, first jump to the desired frequency, then enter a very high frequency metastable state and then jump back to the fundamental frequency. With a small amount of practice, these metastable states, which last for approximately 100 to 500 ms, can be easily detected on an oscilloscope. In the third case, the MCU generally takes almost a second to reach steady state, which provides plenty of time for it to attempt operation while the clock is in a metastable state.

2.5.2.6 Using a Canned Oscillator

A second option when using the internal frequency synthesizer circuit is to hold MODCLK high during reset and connect an external clock reference or canned oscillator (a single package that includes the oscillator and required external components) to the EXTAL pin. Leave the XTAL pin floating, but connect the filter circuit shown in **Figure 6** to V_{DDSYN} and XFC. The allowable frequency range is 20–50 kHz.

One manufacturer of canned oscillators is:

2.5.3 Using an External Clock

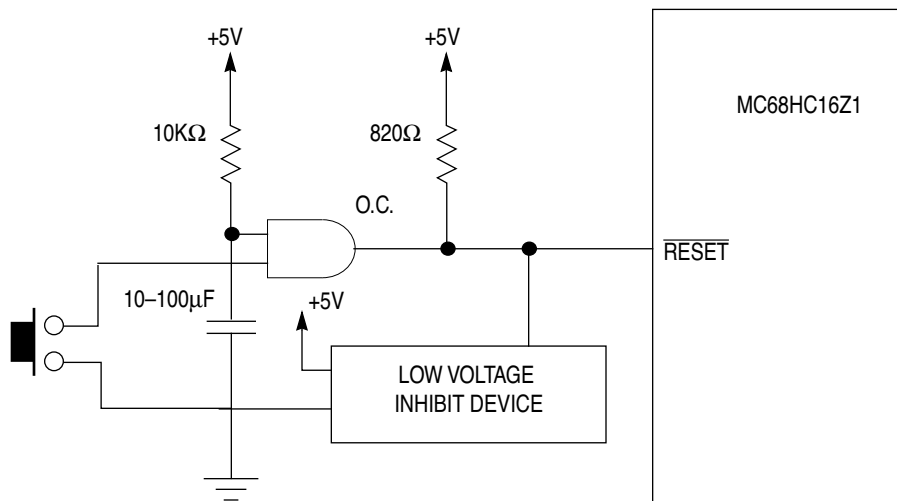
To use an external clock, connect a clock signal to the EXTAL pin and hold MODCLK low during reset. Leave the XTAL and XFC pins floating, but connect V_{DDSYN} to power. The frequency control bits in the SYNCR register have no effect; the signal applied to the EXTAL pin should appear unchanged on the CLKOUT line. The external clock must comply with the following expression.

$$\text{Minimum external clock period} = \frac{\text{Minimum external clock high/low time}}{50\% - \text{percentage variation of external clock input duty cycle}}$$

Minimum external clock high/low time is a specification given in the device electrical characteristics.

2.6 Getting Out of Reset

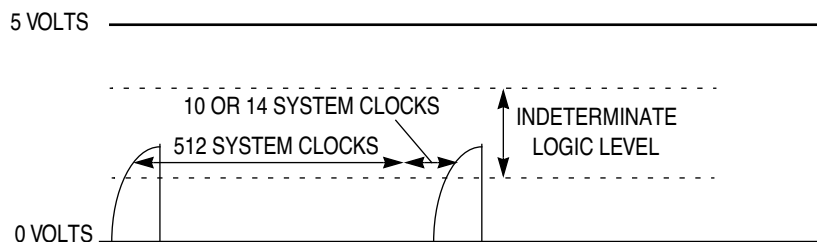
Asserting and releasing the $\overline{\text{RESET}}$ line was once a relatively simple task. However, as microcontrollers have become more complex, bidirectional reset pins have become standard. Bidirectional reset lines allow an external device to reset the MCU and also allow the MCU to assert reset for associated peripherals. Bidirectional pins must be driven with open collector devices. A typical circuit for driving the MCU $\overline{\text{RESET}}$ pin is shown in **Figure 7**. The $\overline{\text{RESET}}$ pin is driven by an open collector device, and it is pulled to a logic 1 by an 820 Ω resistor.



332TUT LV/RESET CONN

Figure 7 Typical MC68HC16Z1 Reset Circuit

When the internal PLL is used to generate the internal system clock, the $\overline{\text{RESET}}$ pin works as follows. At power-up, the MCU drives $\overline{\text{RESET}}$ low. When the PLL locks, the MCU releases $\overline{\text{RESET}}$ for two system clock cycles. If the external pull-up resistor can pull $\overline{\text{RESET}}$ to a logic 1 during the two cycles, the MCU assumes that the reset is a power-on reset rather than an external reset. However, if $\overline{\text{RESET}}$ does not rise to a logic 1 during the two cycles, the MCU assumes that the reset is an external reset and drives $\overline{\text{RESET}}$ to a logic 0 for 512 clock cycles. After 512 cycles have elapsed, the MCU releases $\overline{\text{RESET}}$ for 10 clock cycles. If $\overline{\text{RESET}}$ is a logic 1 at the end of the 10 cycles, the MCU begins program execution. If $\overline{\text{RESET}}$ is a logic 0 at the end of the 10 cycles, the MCU once again actively drives $\overline{\text{RESET}}$ low for 512 clock cycles. This cycle repeats until $\overline{\text{RESET}}$ is finally perceived to be at a logic 1. **Figure 8** shows the waveform that is produced on the $\overline{\text{RESET}}$ line when the pull-up resistor is too large and pull-up current is inadequate.



332TUT RESET LEVEL TIM

Figure 8 RESET Waveform Caused by Weak Pull-Up

If the PLL circuit is not used, and an external clock at the desired frequency of the system clock is applied to EXTAL prior to start-up, the start up sequence is the same except that the MCU recognizes the clock immediately instead of waiting for the PLL to lock.

2.7 Power Supply

Always connect all power and ground pins to power sources. Internal power buses only serve about 8 – 10 pins each. The power and ground pins are usually not connected together within the device. If any power pin is left floating, the pins served by the floating power pin can receive power from internal circuitry such as internal protection diodes. However, the current path will usually have several diode drops resulting in a low output high voltage (about 3 volts) on associated output pins.

2.7.1 Low Voltage Inhibit Devices

A low voltage inhibit (LVI) device (also referred to as a reset supervisor circuit) protects the MCU by keeping it in reset until full voltage is applied and by forcing an external reset as soon as power starts to fall. This prevents the MCU from going into an indeterminate state due to a power supply failure or slow power supply ramp-up time. It is a good idea to use an LVI device since the MCU is not guaranteed to stay in reset when power is below V_{DD} . In fact the actual voltage level that causes the MCU to go into reset is not a specified parameter, and the MCU may continue to try to operate even when power dips below V_{DD} .

A number of manufacturers make LVI devices that can be used with the MCU.

Analog Devices — (617) 461-3392

LVI part numbers are ADM698 and ADM699. These devices require pull-up resistors.

Dallas Semiconductor — (214) 450-0448

Various reset supervisor circuits. Part numbers DS1233A, D, and M do not require pull-up resistors.

Linear Technologies — (408) 432-1900

LVI part numbers are LTC692 and LTC693. These devices require a pull-up resistor.

Maxim — (800) 998-8800 or (408) 737-7600

Various reset supervisor circuits. MAX 690 and MAX 700 series devices require pull-up resistors, but MAX 809 devices do not.

Freescale Semiconductor, Inc. — (408) 432-1900

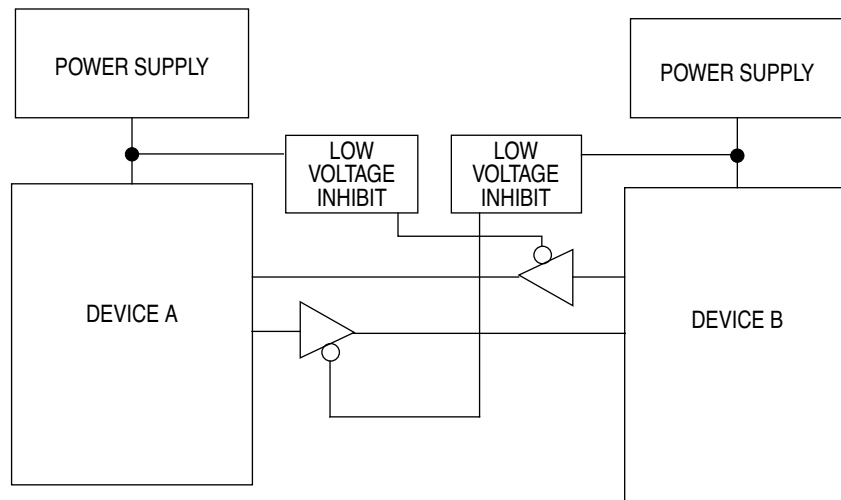
One reset supervisor circuit part number is MC34064. It requires an external pull-up resistor.

2.7.1.1 Using LVI Devices with External Oscillators

An LVI device provides an extra degree of protection when an external oscillator that has an independent power supply is used to generate the system clock. In this case, the LVI device ensures that the oscillator does not power up before the MCU.

2.7.1.2 Using LVI Devices with Multiple Power Supplies

Take special precautions when system components that are connected to each other have separate power supplies. Generally, one power supply will reach operating voltage more quickly than another. A device connected to this fast supply can begin to operate before devices connected to a slower supply have reached operating voltage. If a device connected to a fast supply drives logic one levels to a device connected to a slow supply, the input protection diodes of the slow -starting device can be momentarily forward biased, and significant current can be injected into the device substrate. In the case of an MCU, the injected current can cause internal nodes to be improperly charged or discharged. Since this action is random, it is impossible to predict what will happen when injection occurs. Usually, the processor will fail to fetch opcodes. **Figure 9** shows how to use LVI devices to prevent this problem. Each power supply is monitored by a separate LVI device. Signals from other boards are inhibited until correct operating voltage is applied.



332TUT DUAL RESET CONN

Figure 9 Using LVI Devices with Multiple Power Supplies

2.8 Designing for Electromagnetic Compatibility

Because of the fast clock speed and relatively short rise and fall times of MCU signals, the designer must consider electromagnetic compatibility (EMC) issues. All high-speed digital devices radiate noise, and if FCC compliance is required, the designer must do everything possible to limit emissions from the MCU. Use of a four-layer board is probably the best single option the designer has. Although a two-layer board will work, a multilayer PCB is much more effective at both protecting the MCU from emissions, and reducing emissions from the MCU. EMC compatibility is a complex topic, and this tutorial can present only a brief overview of EMC design techniques.

2.8.1 Reducing Power Supply Noise

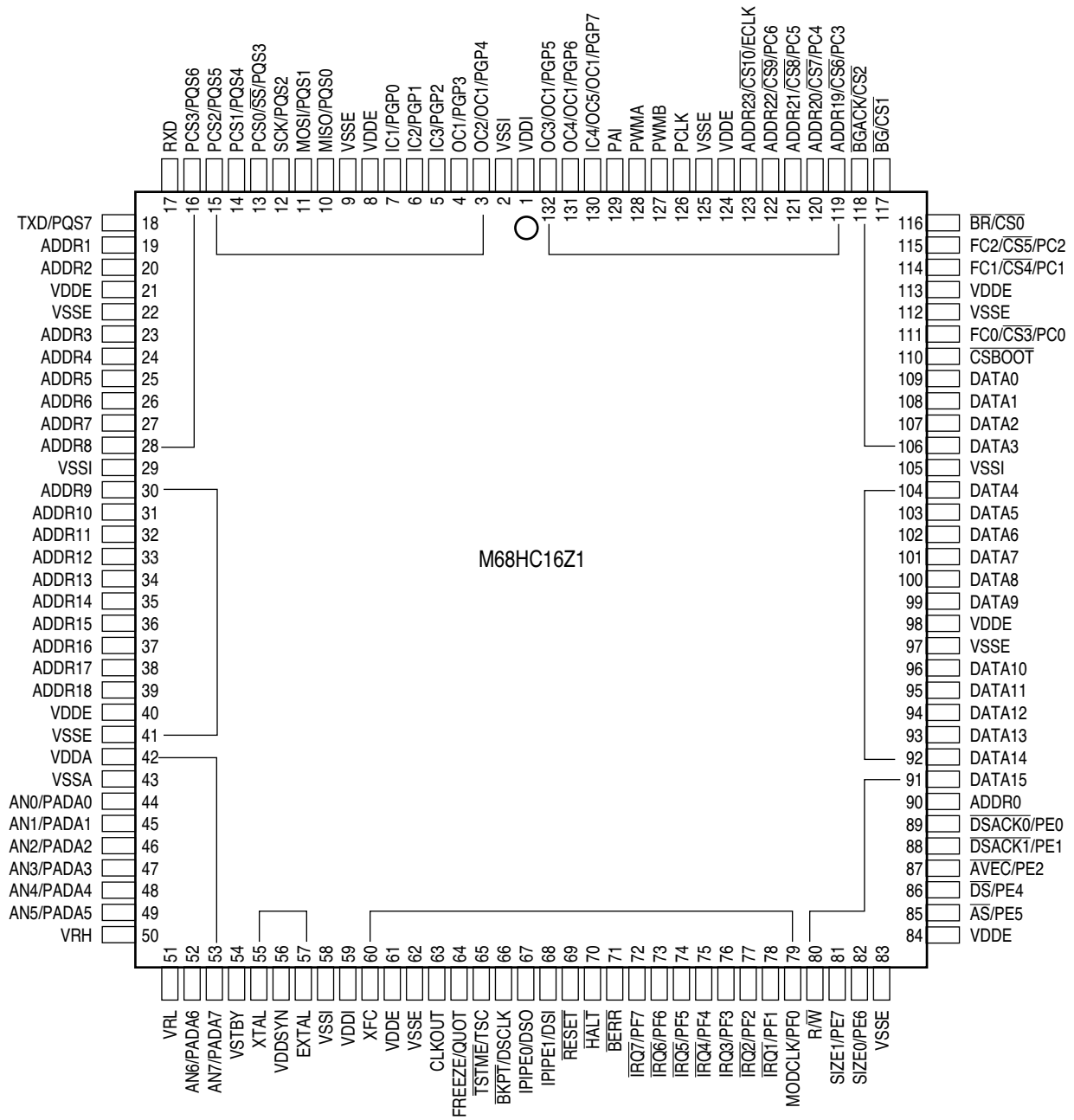
The MCU is very susceptible to noise created by large or rapid fluctuations in current through a particular power supply pin. The power supply pins are divided up into V_{DDE}/V_{SSE} and V_{DDI}/V_{SSI} . The V_{DDE}/V_{SSE} pins power the external drivers and pins, while the V_{DDI}/V_{SSI} pins power the internal peripherals and core of the MCU. It is very important to keep the V_{DDI}/V_{SSI} pins free of noise as the CPU is generally

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more sensitive to power supply noise than the port drivers. When designing a multilayer board, simply route the power and ground pins directly to the power and ground planes; when designing a two-layer board, however, it is best to isolate the power bus that serves the core of the chip from the power bus that serves the port drivers.

Figure 10 shows groups of pins that are powered by the same supply pins. Although only the 132-pin plastic surface mount package is shown, the groups for the 144-pin package are the same. In each group, the V_{DDE} and V_{SSE} pins that power a particular group are shown in bold face type. The V_{DDI} and V_{SSI} pins are labeled as such. EXTAL and XTAL are powered only by V_{DDSYN} .

When control of noise on the power buses is important, it is possible to isolate sections of the chip that are particularly noisy. The data and address buses are particularly noisy because they continually change state, and the same can be true of serial ports and timer pins. The amount of noise generated by a particular pin is dependent upon the load being driven and the switching frequency. A designer who knows which power and ground connections serve particular pins can shield other signal conductors from these noisy lines.



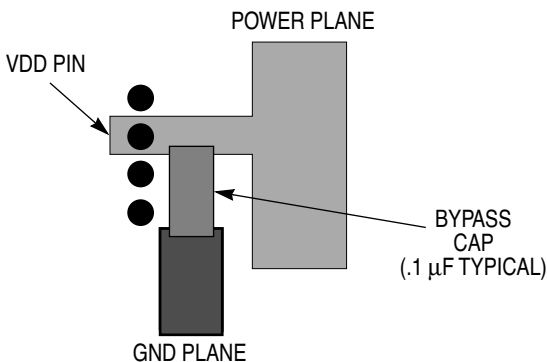
Z1 132-PIN QFP

Figure 10 Pinout of MC68HC16Z1 132-Pin Package

To control power supply/ground noise, use dedicated ground and supply planes. When designing a two-layer board, make the power and ground traces on the PCB as large as practical and connect a bypass capacitor to each power supply pin. The V_{DDI}/V_{SSI} and V_{DDE}/V_{SSE} supply pins should all have dedicated filter capacitors, and, ideally, all supply pins should be connected to the supply at a single location. A recommended layout technique is shown in **Figure 11**. Essentially, the bypass capacitor should be positioned so that it serves the power pin itself rather than the surrounding metal trace. This is accomplished by running a specific conductor to the power pin and then locating the bypass capacitor as close to the power pin as possible.

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Another way to control power supply noise created by the MCU is to put a small inductor in series with the power supply lines for the port drivers. This method can help control noise on the power traces of the PCB. However, it should be used only as a last resort, because it can introduce other noise problems. Also, a series inductor in the power supply line will probably have little effect on radiated noise, which is generally a result of the port driver switching speed. Limiting instantaneous current change by putting an inductor in series with the power supply pin for the port will not appreciably affect the current through a particular driver because the integrated circuit generally has enough internal capacitance to support an instantaneous current surge while the driver switches.



332TUT VDD LAYOUT

Figure 11 Proper Placement of a Bypass Capacitor

The V_{DDSYN} and V_{STBY} supply pins should be separated and isolated from V_{DD} with a low pass filter. Any supply noise present on V_{DDSYN} will translate into shifts in the system clock generated from the PLL. Always supply power to V_{DDSYN} , even when using an external oscillator and bypassing the internal PLL.

2.8.2 Suggestions for Reducing Emissions

In general, follow standard design practices for EMC. A list of techniques that are often used in board design follows. These techniques are guidelines for good design, not strict rules, and are not specific to designs that incorporate the MC68HC16Z1.

- Minimize the number of devices on the board. Capacitive coupling tends to occur around the holes that connect a particular layer of the board to the power and ground planes.
- Use a canned oscillator instead of a crystal, to reduce emissions from the oscillator. If a crystal circuit must be used, locate it as centrally as possible.
- Use a four layer PCB. As a general rule, a multilayer board is at least 10 times better than a two layer board for both emissions and immunity. To reduce emissions even further, enclose the signal traces between the power and ground planes because the added capacitance between the signal trace and ground results in a lower characteristic impedance.
- Plot thick layout lines with the layout program, then cut the actual traces on the board thin.
- If a trace that conducts a high frequency signal must be routed on the surface of the PCB, route ground traces parallel to it to reduce radiation and crosstalk. Connect the ground traces to ground planes at varied intervals not to exceed the wavelength/4 at the highest frequency or harmonic expected.
- Round off PCB trace corners as much as possible to reduce the amount of excess capacitance that is introduced to the trace at corners.
- Make spacing between adjacent active traces greater than the trace width to minimize crosstalk.
- Put a chassis ground ring on the periphery of each layer of the PCB, to intercept the field coming off the board. Interconnect these rings with small ceramic capacitors.
- Use ferrite chokes when troubleshooting. Placing a choke around a signal line and the return conductor carrying a differential signal causes fields developed in the ferrite core by the opposing currents to cancel. Ferrite chokes can also be used on input/output lines. Because board-mounted chokes in-

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- crease the number of holes connecting to the supply planes, they should be used only as a last resort.
- Localize any high frequency circuits, such as the clock and address or data buses. Decouple locally using high frequency filters such as ferrite chokes or damping resistors. Be sure to separate the high speed and low speed circuits.
- Turn off any output signals (such as ECLK) that are not used.
- Shield the board externally.
- Reduce power supply noise as much as possible.

2.8.3 Other Sources of Information

Freescale publishes two application notes on related subjects:

Designing for Electromagnetic Compatibility with HCMOS Microcontrollers (AN1050)

Transmission Line Effects in PCB Applications (AN1051).

EDN Magazine offers a reprint of the "Designer's Guide to Electromagnetic Compatibility."

Refer to **6 Sources of Information** for ordering information.

EMC consultants are probably the best source of information on this topic, since they specialize in EMC and RFI problems. Consultants can help troubleshoot real problems, conduct seminars, and provide tutorials, books and software on the subject.

2.9 Connecting Memory and Peripherals

The MCU offers many different ways to configure memory and peripherals. The user can decode the external bus interface externally or use chip-selects. Since it is usually more efficient to use the chip-selects, this tutorial does not cover signal decoding. However, the *SIM Reference Manual* (SIMRM/AD) gives detailed explanations and examples of how to decode signals for both 8- and 16-bit memory devices on pages 5-31 through 5-34. These examples also show how to use function code pins to determine which address space is being accessed.

The MC68HC16Z1 can generate 12 chip-select signals. These signals can be used to expand the system. A chip-select signal selects and enables a particular peripheral device or memory chip for data transfer. The chip-select circuits can also be programmed to generate data transfer and size acknowledge (\overline{DSACK}), interrupt acknowledge (IACK), and autovector (AVEC) signals.

2.9.1 Using Chip-Selects to Generate \overline{DSACK}

Chip-select circuits can be configured to wait for external data and size acknowledge signals on the $\overline{DSACK1}$ and $\overline{DSACK0}$ lines or to generate internal \overline{DSACK} signals. A circuit can generate an internal \overline{DSACK} signal even if the pin is configured for discrete output or alternate function.

The chip-select logic can wait for a certain number of clock states before generating \overline{DSACK} . These states are called wait states. Wait states are inserted after state 3 of a read or write bus cycle. A normal bus cycle lasts three clock cycles plus the number of wait clock cycles. The chip-select logic can insert a maximum of 13 wait states.

2.9.1.1 The Relationship Between Wait States and Memory Speed

Memory speed and the number of wait states necessary are related by the following equations:

$$\text{Address access time} = (2.5 + WS) \times t_{CYC(\min)} - t_{CHAV(\max)} - t_{DACL(\min)}$$

$$\text{Chip-select access time (MCU read cycle)} = (2 + WS) \times t_{CYC(\min)} - t_{CLSA(\max)} - t_{DACL(\min)}$$

$$\text{Chip-select access time (MCU write cycle)} = (2 + WS) \times t_{CYC(\min)} - t_{CLSA(\max)} + t_{CLSN(\min)}$$

In the equations, WS is the number of wait states programmed in the \overline{DSACK} field. For fast termination mode, WS = -1, for zero wait states, WS = 0, for one wait state, WS = 1, etc. Also, it is assumed that chip-select assertion is based on address strobe. If it is based on data strobe, add $2(t_{CYC})$ to t_{CLSA} for

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the write cycle chip-select access time. The other known parameters are shown in **Table 2**.

Table 2 Parameters Needed for Calculating Memory Access Times

Parameter	Symbol	16.78 MHz		20.97 MHz	
		Min	Max	Min	Max
Clock Period	t _{CYC}	59.6 ns	—	47.7 ns	—
Clock Low to \overline{AS} , \overline{DS} , \overline{CS} Asserted	t _{CLSA}	2 ns	25 ns	0	23 ns
Data In Valid to Clock Low (Data Setup)	t _{DICL}	5 ns	—	5 ns	—
Clock High to Address, FC, SIZE, \overline{RMC} Valid	t _{CHAV}	0	29 ns	0	23 ns
Clock Low to \overline{AS} , \overline{DS} , \overline{CS} Negated	t _{CLSN}	2 ns	29 ns	2 ns	23 ns

MCU read cycle access time is used to determine the number of wait states needed for a given memory speed, because it is longer than write cycle access time, and is thus the limiting factor.

As an example, the equations below are solved for zero wait states, assuming 16.78 MHz timing:

$$\text{Address access time} = 2.5 \times 59.6 \text{ ns} - 29 \text{ ns} - 5 \text{ ns} = \underline{115 \text{ ns}}$$

$$\text{Chip-select access time (MCU read cycle)} = 2 \times 59.6 \text{ ns} - 25 \text{ ns} - 5 \text{ ns} = \underline{89.2 \text{ ns}}$$

$$\text{Chip-select access time (MCU write cycle)} = 2 \times 59.6 \text{ ns} - 25 \text{ ns} + 2 \text{ ns} = \underline{96.2 \text{ ns}}$$

The equations can also be solved for the number of wait states needed, given the memory speed. Use **Table 3** to find the number of wait states required for a particular memory speed. For example, with a 16.78 MHz clock, a memory with a write cycle time of 130 ns requires one wait state, since 130 ns is between 89.2 ns and 148.8 ns.

Table 3 Memory Access Times in Nanoseconds

Wait States	16.78 MHz		20.97 MHz	
	Chip-Select Read Access (Memory Write Access)	Address Access	Chip-Select Read Access (Memory Write Access)	Address Access
F.T.	29.6	55.4	19.7	43.55
0	89.2	115.0	67.4	91.25
1	148.8	174.6	115.1	138.95
2	208.4	234.2	162.8	186.65
3	268.0	293.8	210.5	234.35
4	327.6	353.4	258.2	282.05
5	387.2	413	305.9	329.75
6	446.8	472.6	353.6	377.45
7	506.4	532.2	401.3	425.15
8	566.0	591.8	449.0	472.85
9	625.6	651.4	496.7	520.55
10	685.2	711	544.4	568.25
11	744.8	770.6	592.1	615.95
12	804.4	830.2	639.8	663.65
13	864.0	889.8	687.5	711.35

2.9.2 Using Chip-Select Signals to Enable Boot Memory

The MCU \overline{CSBOOT} chip-select circuit is always enabled from reset. Because the internal SRAM mod-

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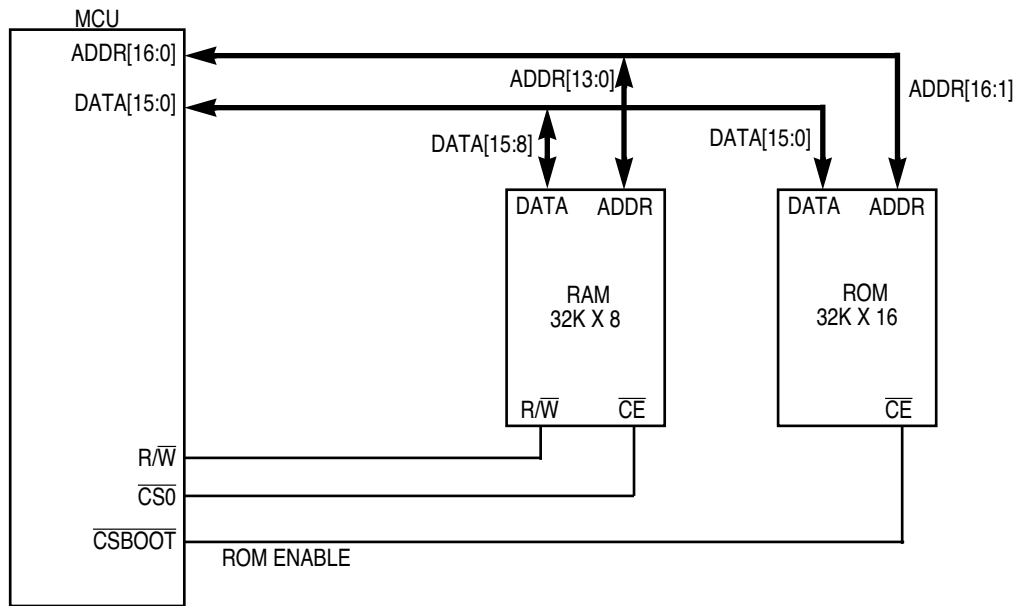
When the $\overline{\text{CSBOOT}}$ signal is disabled out of reset, the $\overline{\text{CSBOOT}}$ signal is generally used to select an external boot ROM. The $\overline{\text{CSBOOT}}$ chip-select circuit features hardware-controlled selection of 8-bit or 16-bit bus width. Bus width is controlled by the state of the DATA0 line at the release of the $\overline{\text{RESET}}$ signal. The default bus width out of reset is 16 bits because the DATA0 line is pulled up to logic level 1 internally; however, the internal pull-up circuit is weak, so it is best to follow the recommendations in **2.1 Using Data Bus Pins to Configure the MCU**.

For example, to design a system that uses 16-bit boot memory built from two 27C512 byte EPROMs, connect the chip-select and output enable lines of the EPROMs to the $\overline{\text{CSBOOT}}$ line. Also connect MCU address lines ADDR[1:16] to address lines [0:15] of the memories. Do not use ADDR0 of the MCU. This system will be word accessible only.

In general, the MCU cannot make byte writes to word memory selected by $\overline{\text{CSBOOT}}$. This lack of byte write capability is not much of a practical limitation since the $\overline{\text{CSBOOT}}$ signal is generally used for read-only access, and all CPU32 instructions must be word-aligned. However, if byte-write capability is required, the SIZ and $\overline{\text{CSBOOT}}$ signals can be used to generate “high byte” and “low byte” chip-select signals. The only other way to modify individual bytes is to use word moves, being careful to write the original data back to the unchanged byte.

2.9.3 Using Chip-Select Signals to Enable External Memory

Chip-select signals can be configured for 8-bit or 16-bit ports. To use an 8-bit memory, connect the memory element’s data lines to the upper half of the MCU data bus (DATA[15:8]). The MCU reads and writes an 8-bit port on the upper half of the data bus. During write cycles, data is echoed on the lower half of the data bus as well. Connect address line ADDR0 of the MCU to A0 of the memory. An example configuration is shown in **Figure 12**. To use a 16-bit memory, connect the memory data lines to MCU data bus (DATA[15:0]). Connect address line ADDR1 from the MCU to A0 of the memory.



332TUT EXT MEM CONN 1

Figure 12 Using Chip-Select Signals to Enable 8-Bit RAM

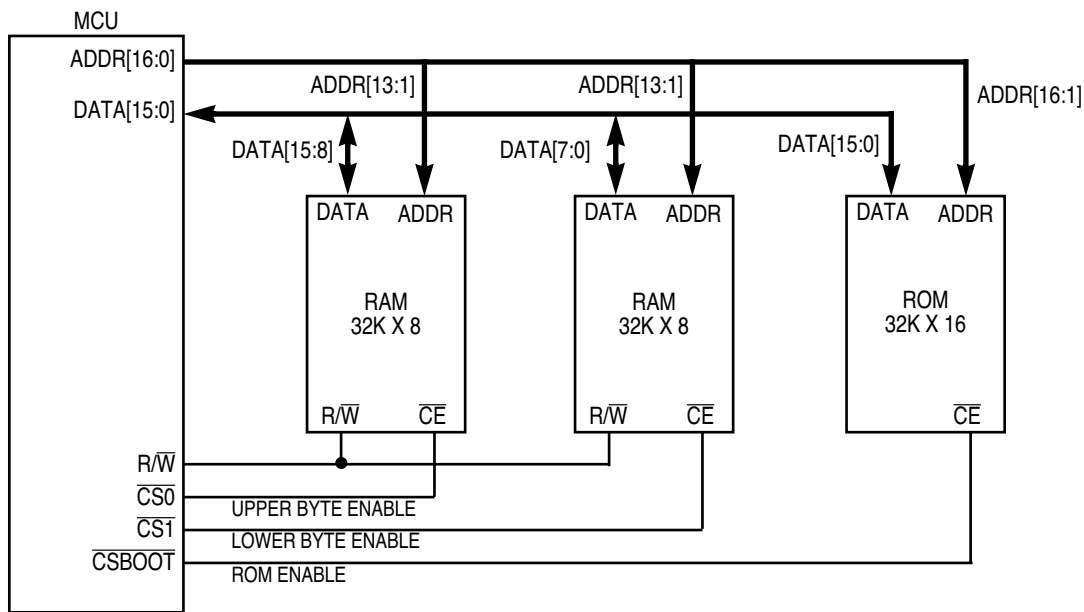
2.9.3.1 How to Construct Word Memory from Two Byte Memories

For chip-select signals other than $\overline{\text{CSBOOT}}$, forming word memory that is byte-accessible from two

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byte-wide devices is simple. Use a separate chip-select pin for each device, and configure chip-select logic to decode the upper and lower bytes, respectively. Each of the chip-select circuits must be configured as a 16-bit port, even though only eight bits of memory are being accessed. This allows both byte and word writes — if both memories were connected to the same chip-select line, byte writes would corrupt the adjacent byte. This function can also be implemented in external logic by gating a single chip-select line with the MCU ADDR0 line to select upper and lower bytes. For ROM memory a single-chip-select can be used to enable both byte-wide ROMs, as the MCU uses only the required byte on the data bus during a byte read and ignores the remaining byte.

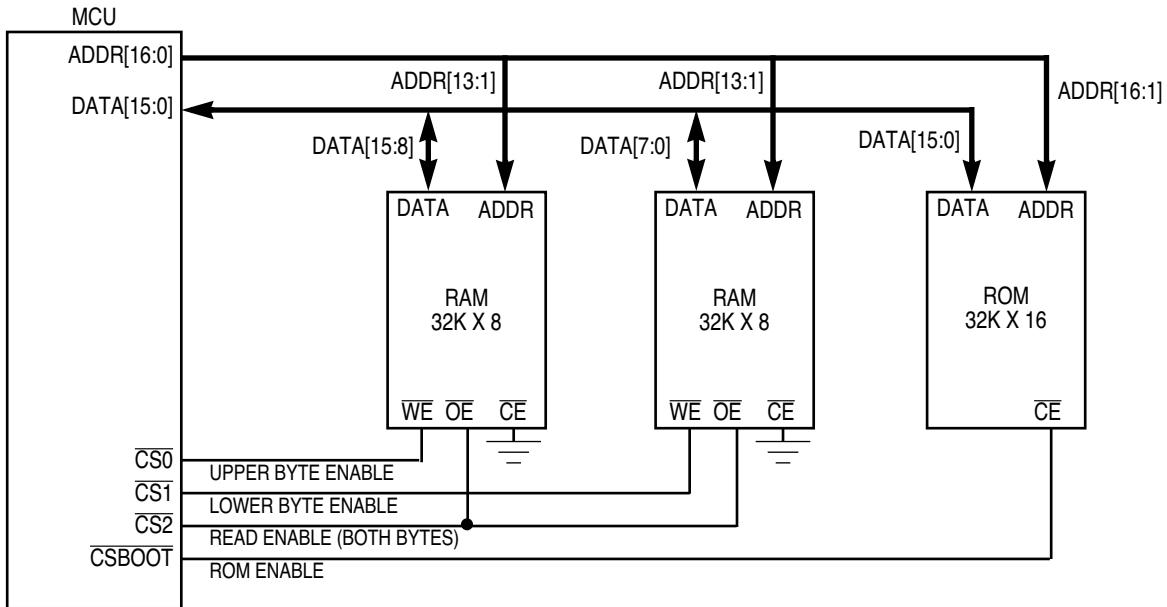
Figure 13 illustrates how to connect two 8-bit memories as one 16-bit port. It also shows the connections necessary for a 16-bit memory. In this example configuration, $\overline{CS0}$ is connected to the chip enable pin \overline{CE} of the first RAM chip and $\overline{CS1}$ is connected to the chip-enable pin of the second RAM chip. This effectively makes $\overline{CS0}$ the upper byte enable and $\overline{CS1}$ the lower byte enable. The R/\overline{W} line of the MCU is connected to the R/\overline{W} lines of both RAM chips. \overline{CSBOOT} is connected to the ROM enable. ADDR[13:1] of the MCU are connected to address lines [12:0] of each RAM chip, and ADDR[16:1] of the MCU are connected to address lines [15:0] of the ROM.



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Figure 13 Configuring 16-Bit Memory with 8-Bit RAMs — Common R/\overline{W} Input

Another common configuration is shown in **Figure 14**. Here, the chip enables (\overline{CE}) are always asserted, the write enable (\overline{WE}) for upper byte access is connected to $\overline{CS0}$, the write enable for lower byte access is connected to $\overline{CS1}$, and the read enable (\overline{OE}) for both upper and lower byte accesses are connected to $\overline{CS2}$. See **4.2.10 Example of SIM Initialization** for software to initialize this example system.



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Figure 14 Configuring 16-Bit Memory with 8-Bit RAMs — Separate Read and Write Enables

2.10 Using External Interrupts

The MCU has seven external interrupt lines, $\overline{\text{IRQ}}[7:1]$. These are active low signals that cause the processor to jump to a special routine and then return to the main code. The following paragraphs cover the basic elements of servicing external interrupt service requests. Refer to **4.1.2 Exceptions** for more detail. Chapter 6 of the *SIM Reference Manual* (SIMRM/AD) has an in-depth explanation of how to use external interrupts.

2.10.1 Interrupt Priority Levels

An interrupt can be recognized on one of seven priority levels. These levels correspond to the numeric values of the external interrupt request lines. Level one ($\overline{\text{IRQ}}1$) has the lowest priority; level seven ($\overline{\text{IRQ}}7$) has the highest priority level. Levels one through six can be masked by the interrupt priority level (IPL) field contained in bits 7 through 5 of the condition code register (CCR). The level specified in the IPL field and all levels below it are masked and are not recognized by the CPU. Level 7 is the only exception to this rule; it cannot be masked. Out of reset, the IPL field is set to level 7. Thus, levels 1 through 6 will not be recognized unless the IPL field is re-written to a lower value. The priority mask value can be changed by writing a new value into the appropriate bits of the CCR.

EXAMPLE:

To allow interrupts on levels 6 and 7 only, mask out levels 5 and below.

```
ANDP #$FF1F
ORP  #$00a0
```

During interrupt processing, a copy of the current CCR is saved onto the stack, and the priority level of the interrupt being serviced is written to the IPL field of the CCR. This means that during execution of an interrupt routine, only higher priority interrupts can be recognized. However, the CPU16 guarantees that at least the first instruction of an interrupt routine will be executed before another interrupt can preempt it. This allows the interrupt routine to inhibit other interrupts (except for level 7) during the routine by re-writing the IPL field in the CCR.

2.10.2 Interrupt Arbitration Field

Most modules in the MCU can request interrupt service. The CPU treats external interrupts as interrupt service requests from the system integration module (SIM). The interrupt arbitration (IARB) field in the configuration register of each module determines which module's interrupt requests take precedence when the CPU receives more than one request at the same priority level. In order for interrupt requests to be acknowledged, each module must be assigned a unique IARB number between \$1 (lowest precedence) and \$F (highest precedence). Out of reset, the SIM IARB field has an initial value of \$F, while other modules have initial IARB values of \$0.

2.10.3 Interrupt Vectors

Vectors are 16-bit addresses that point to the interrupt service routines (and other exception handlers). They are stored in a data structure called the exception vector table. There are 256 vector addresses in the exception vector table; of these, 199 can be used for interrupts. The base address of the exception vector table is determined by the value stored in the vector base register. A vector number is used to calculate the vector address, i.e., a displacement into the exception vector table.

2.10.4 The Interrupt Acknowledge Cycle

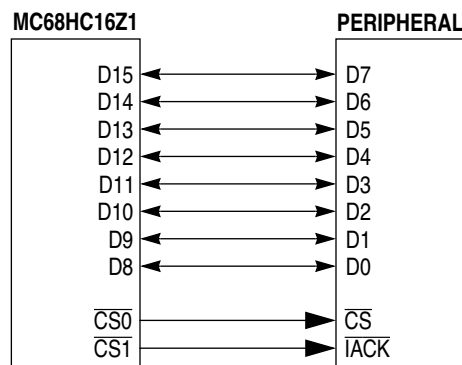
After the CPU recognizes a valid interrupt request, the CPU begins the interrupt acknowledge (IACK) cycle. The CPU changes the IPL mask value to the level of the acknowledged interrupt to preclude lower-or-equal priority interrupt requests, then initiates a read cycle in CPU space. Since there is no dedicated IACK pin on the MCU, an external IACK signal is usually provided by a chip-select pin.

Vector numbers can be supplied by the device requesting interrupt service, or they can be generated automatically. Vector numbers supplied by the device cause the CPU to access one of 192 user vectors in the exception vector table; automatically generated vectors cause the CPU to access one of the 7 autovectors in the table. Each method of vector number acquisition requires a different form of IACK cycle termination. If a vector number is supplied, either the requesting device must terminate the IACK cycle with a \overline{DSACK} signal or the chip-select logic must generate the \overline{DSACK} signal internally. If an autovector is used, an external device can assert the \overline{AVEC} signal or an \overline{AVEC} signal can be generated by the chip-select logic. Since normal bus cycles occur in user or supervisor space, but an IACK cycle occurs in CPU space, the same chip-select circuit cannot be used to terminate both an IACK cycle and a normal bus cycle.

2.10.4.1 User Vectors

Once an interrupting device has placed a user vector number on the external data bus in response to an IACK signal from the MCU, either the device must terminate the IACK cycle with \overline{DSACK} , or the chip-select logic must generate \overline{DSACK} internally. When the bus cycle has been terminated, the vector number is left-shifted once (multiplied by 2) to form the 16-bit vector address. The CPU then saves the current context, loads the 16-bit vector into the PC, and begins to execute the service routine at that address.

An example is shown in **Figure 15**. Chip select 1 is configured for interrupt acknowledge and automatic generation of the \overline{DSACK} signal. It is connected to the IACK pin of the peripheral. Because the processor drives \$FFFFFFx onto the address bus and drives the function code pins to indicate CPU space during an IACK cycle, the chip-select base address register must be programmed to \$FFFX. When the CPU recognizes an interrupt and initiates an IACK cycle, $\overline{CS1}$ is asserted. In response, the peripheral drives an 8-bit vector number onto the data bus. Chip-select logic then terminates the IACK cycle with \overline{DSACK} .



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Figure 15 Chip-Select Line Used for Interrupt Acknowledge

2.10.4.2 Autovectors

When an external device cannot supply a vector number in response to an IACK cycle, an autovector can be used instead. The autovector number is determined by the priority of the interrupt request. For example autovector number 2 corresponds to $\overline{IRQ2}$. In order for an autovector to be automatically used, the IACK cycle must be terminated by an \overline{AVEC} signal. There are two ways to do this: either assert the \overline{AVEC} signal externally or use the internal chip-select circuitry to provide the \overline{AVEC} signal. Once the bus cycle has been terminated, the CPU saves the current context, loads the 16-bit vector into the PC, and begins to execute the service routine at that address. As a side note, internal modules cannot terminate an IACK cycle with \overline{AVEC} , which would cause the CPU to automatically provide the autovector. An internal module must request a particular vector number by writing the appropriate value to its interrupt configuration register. The internal module will then automatically terminate the IACK cycle with \overline{DSACK} and provide the CPU with the vector number as specified by its interrupt configuration register.

One way to use autovectors is to tie the \overline{AVEC} pin to ground. This effectively generates an external \overline{AVEC} signal only in response to all IACK cycles caused by external interrupt service requests. If it is not desirable for all external interrupts to autovector, specific external devices can assert \overline{AVEC} in response to an IACK cycle. However, in this case it is usually easier to set up a chip-select circuit to provide the \overline{AVEC} signal internally.

Perform the following steps to set up a chip-select circuit to generate the \overline{AVEC} signal:

1. Configure the chip-select pin for any of its available functions in the pin assignment register.
2. Program the appropriate base address register to \$FFF8 or higher.
3. Select the following fields in the appropriate option register:
 - A. MODE Bit — select asynchronous mode (%0)
 - B. BYTE Field — select assertion for both bytes (%11)
 - C. R/ \overline{W} Field — select assertion for both reads and writes (%11)
 - D. STRB Bit — select synchronization with \overline{AS} (%0)
 - E. \overline{DSACK} Field — select number of wait states (user specified)
 - F. SPACE Field — select CPU space assertion (%00)
 - G. IPL Field — select interrupt priority level (user specified)
 - H. \overline{AVEC} Bit — enable \overline{AVEC} generation (%1).

See 4.2 Configuring the System Integration Module for a more detailed description of the fields in chip-select option registers.

2.10.5 Level-Sensitive versus Edge-Sensitive Interrupt Pins

Interrupt pins $\overline{IRQ}[6:1]$ are level sensitive. Assertion of an active-low signal connected to one of these

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pins is recognized as a valid interrupt request if the interrupt priority level of the pin is greater than the value of the IPL field in the condition code register (CCR). Once an interrupt service request is recognized, the CCR is copied onto the stack, then the IPL value is changed to match the priority level of the interrupt being serviced. This prevents interrupts of the same or lower priority while the service routine executes. For instance, if the IPL value is \$3, and a level five service request is recognized, the CCR is stacked, then the IPL value is changed to \$5. An RTI instruction at the end of the service routine normally terminates interrupt service. RTI pops the stacked CCR, and thus restores the original IPL value. The IPL field can also be changed by writing to the CCR. If an interrupt service routine writes a lower value to the IPL field while the request signal is still asserted, the CPU recognizes a second service request.

$\overline{\text{IRQ7}}$ is both edge and level sensitive. Level seven interrupts cannot be masked by the IPL field. When a level seven interrupt service request is recognized, the current value of the condition code register is pushed onto the stack, and the IPL value is changed to \$7.

It is very important to make certain that the $\overline{\text{IRQ7}}$ signal be negated before the level seven interrupt service routine ends. A new level seven interrupt will be recognized in the following cases:

If the $\overline{\text{IRQ7}}$ signal negates and is then re-asserted while the interrupt service routine is executing.

If the $\overline{\text{IRQ7}}$ signal remains asserted through the execution of the RTI instruction that ends the service routine.

If the $\overline{\text{IRQ7}}$ signal is asserted and the IPL field is written during execution of the interrupt service routine. This is true even when the mask is re-written to \$7.

Provide for negation of the signal within the service routine, and avoid writing to the CCR during execution of the level seven interrupt service routine.

2.10.6 Checklist for External Interrupt Acknowledge

- **Is the desired pin configured as an interrupt pin instead of an I/O pin?**

The interrupt pins are dual-function pins. Their initial configuration is determined by the state of data bus pin 9 at the release of reset. After reset, their configuration is determined by the port F pin assignment register.

- **Was the starting address of the interrupt routine written to the vector offset address?**

The CPU must be told where the interrupt service routine begins. See **4.1.2 Exceptions** for a more detailed explanation.

- **Is the IARB field in the SIMCR a unique, non-zero value between \$1 and \$F?**

All interrupting modules must have a unique, non-zero value in the IARB field.

- **Is the IPL field in the condition code register set to a value lower than the desired interrupt level?**

The CPU will not recognize an interrupt that is at the same level or lower than the value in the IPL field. Level 7 is the only exception to this rule; it is always recognized.

- **Is the IACK cycle terminated with $\overline{\text{AVEC}}$ or $\overline{\text{DSACK}}$?**

The IACK cycle must be terminated by assertion of the $\overline{\text{AVEC}}$ or $\overline{\text{DSACK}}$ signals, or a chip-select circuit must be configured to assert $\overline{\text{AVEC}}$ or $\overline{\text{DSACK}}$ internally.

- **Does the interrupt request signal negate inside the exception handler?**

It is a good idea to control negation of the interrupt in software. The interrupt should be negated before the RTI instruction.

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3 Establishing Communication

3.1 Communicating with the Target Board

After a target board has been built, it is generally necessary to communicate with it for debugging purposes. Although a designer can write a ROM monitor to communicate with the MCU via the serial port, it is simpler and often more effective to use an emulator or the CPU16 background debug mode (BDM) for communication.

3.1.1 Using an Emulator

An emulator is a direct replacement for the chip that is used to evaluate both software and signals on the target board. Emulators can be very sophisticated and costly, but are very useful in tracking down design problems because they allow the designer to see exactly what the MCU is doing at every step of operation. When both the board and code are fully debugged, the emulator is removed and the MCU is placed on the board.

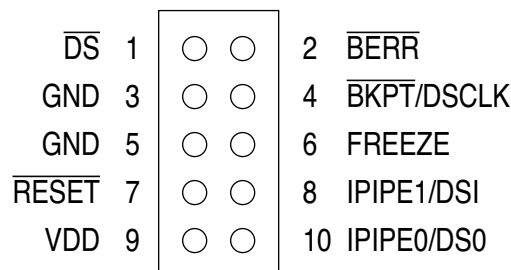
3.1.2 Using Background Debug Mode

Background debug mode is a special CPU operating mode that allows an external host to take control of the MCU. BDM is a very useful tool for debugging. During BDM operation, normal instruction execution is suspended, and microcode executes built-in debugging instructions under external control. Since BDM suspends processor execution, an external host can examine and change memory and registers. BDM instructions and the protocol required to use them are described in detail in the *CPU16 Reference Manual (CPU16RM/AD)*. AN1230/D, *A BDM Driver Package for Modular Microcontrollers*, shows how to implement a BDM communication interface using C-language drivers.

While a BDM interface is relatively easy to implement, ready-made BDM interfaces are inexpensive and reliable. Freescale sells the M68ICD16 BDM debugger made by P&E Microcomputer Systems. The M68ICD16 consists of the necessary cable and software to implement BDM debugging on an IBM-compatible PC. All the discussions in this section assume that M68ICD16 is being used.

3.1.2.1 BDM Signals

To use BDM, simply connect ten MCU lines to pins on the development board that are spaced so that a female Berg connector can plug into them. **Figure 16** shows the pinouts for the recommended 10-pin BDM connector. **Table 4** describes the BDM signals.



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Figure 16 10-Pin BDM Connector

Table 4 BDM Connections

10-Pin Connector	Signal	Use
1	\overline{DS}	Data strobe
2	\overline{BERR}	Output from ICD to \overline{BERR} input
3	GND	Ground reference
4	$\overline{BKPT}/DSCLK$	Output from ICD to \overline{BKPT} input; assertion causes MCU to first enable and then enter background mode. Once in BDM, this pin becomes the serial clock.
5	GND	Ground reference
6	FREEZE	Output from MCU indicating whether it is operating normally or is in BDM
7	\overline{RESET}	Device reset
8	IPIPE1/DSI	Serial input data to the MCU in BDM
9	V_{DD}	Device operating voltage
10	IPIPE0/DSO	Serial output data from the MCU in BDM

Only ten pins on the board, a special cable, and software are needed to debug. The M68ICD16 cable has a 10-pin female connector on one end and a PAL with a 25-pin connector on the other end. The 10-pin connector will plug directly into a male header or connector with the layout shown in **Figure 16**. The PAL end of the cable plugs into the parallel port of a PC. The PC runs the debugger software that controls the MCU in BDM.

3.1.2.2 How BDM Works

The debugger causes the MCU to enter debugging mode by driving the \overline{BKPT} pin low at the release of the \overline{RESET} signal. Reset causes the MCU to fetch the reset exception vectors, load the program counter and stack pointer, then fetch the first instruction pointed to. Since the SRAM module is disabled out of reset, reset vector fetches are made from external memory enabled by the CSBOOT signal. If the CSBOOT chip-select circuit is configured to enable a 16-bit port (DATA0 = 1 at release of \overline{RESET}), the first word of the instruction is fetched, however, if the CSBOOT chip-select circuit is configured to enable an 8-bit port (DATA0 held low at the release of \overline{RESET}), the MCU fetches the first byte of the instruction. The MCU then enters BDM.

At this point the debugger causes the MCU to fetch several instructions, which are displayed in the debugger window on the computer screen. If valid stack pointer and program counter values are present, and a valid program is resident at the address pointed to by the initial PC value, the debugger will display the code beginning at the program counter address.

If the initial stack pointer and program counter values are not valid, however, or if the external memory is either not connected or uninitialized when the fetches are made, it is very likely that the initial SP and PC values will be \$FFFF, and that both the initial SK and PK values will be \$FF. CSBOOT is the only chip-select circuit that is active out of reset, and it enables only the first one Mbyte of memory. When the first instruction fetches are made at \$FFFFFF, there will be nothing to generate \overline{DSACK} and terminate the bus cycle, and the debugger software will force a bus error. Should this occur, the debugger generally displays a series of "Memory implementation error: debugger supplied \overline{DSACK} " messages on the computer screen. After the debugger software has finished making the scheduled number of program fetches, the error messages will stop, and the MCU will be in BDM waiting for the next debugger command. However, additional errors will occur if the next command is an external memory access because the program counter and stack pointer values are invalid.

When using a software background mode debugger to boot an MCU from external RAM or uninitialized ROM, it is imperative that the following actions be taken immediately after starting the debugger:

1. Load a value into the stack pointer. It must point to a modifiable memory address.

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2. Load the address of the first instruction to be executed into the program counter.

The debugger should now work reliably. That is, programs can be downloaded into the RAM and executed. Alternatively, write the reset vector to memory location \$000000 and then reset the MCU. The reset vector is discussed in detail in **4.1.3.1 Initializing the Reset Vector**.

3.2 Communicating with Freescale Boards

Third party vendors sell many types of development tools to help establish communication with the MCU. These tools are described in the Freescale *Microcontroller Development Tools Directory*. However, this tutorial focuses only on Freescale evaluation boards.

3.2.1 The M68HC16Z1EVB

The M68HC16Z1EVB is an evaluation board that consists of a platform board with the processor held in place by a socket. The board has logic analyzer connectors and sockets for external memory. It also has a built-in background debug mode (BDM) connector for use with a debugger. The necessary logic is already on the board, so the user can use a standard 25-pin connector cable and does not need an ICD16 cable with the 10-pin connector.

To run the board as a stand-alone system and not use BDM, simply remove the PAL (U5) that is socketed onto the EVB. Then change jumpers J1 and J4 from the pseudo-ROM position to the EPROM position. On some older boards, the PAL may be soldered to the EVB. In this case, configure the PAL so that its inputs appear as if they are connected to the PC. Connect the following pins to ground and +5 volts as shown:

ground: DB25 pins 6, 8, 21

PAL pins 6, 10, 11

+5 volts: DB25 pins 4, 7, 13

PAL pins 4, 9, 20

3.2.2 The M68MEVB1632

The M68MEVB1632 is a newer and more sophisticated development board than the M68HC16Z1EVB. It consists of a platform board (PFB), a plug-in daughtercard called the personality board (MPB), and the M68ICD16 debugger. The PFB has memory sockets, logic analyzer connections, and jumpers which allow the user to select the state of critical boot-up signals such as the data bus pins and MOD-CLK. The MPB contains the MCU and crystal. The system is very versatile because there are MPBs for a number of different devices, and several MPBs can be used with the same PFB.

3.2.3 The MMDS1632

The MMDS1632 is an emulator that provides high-speed, real-time hardware and software emulation for the target system. It replaces the MCU completely. It is designed to work with a package-specific personality board (PPB) and the MPB. Both of these boards must be purchased separately. The MPB is not necessary if the user has a target board already built. In this case, a connection from the MMDS1632 can be soldered or socketed to the connections intended for the MCU. Contact a local Freescale sales office for more information on the MMDS1632.

4 System Initialization

4.1 Configuring the Central Processing Unit

For a detailed overview of the CPU16, refer to *An Introduction to the HC16 for HC11 Users, Transporting M68HC11 Code to M68HC16 Devices, CPU16 Reference Manual, and Using M68HC16 Digital Signal Processing to Build an Audio Frequency Analyzer*. These documents contain in-depth discussion of

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the CPU, including topics such as the CPU16's DSP instructions and how they can be applied in a real system, the architectural differences between the M68HC11's CPU and the CPU16, the CPU16 instruction set and the different addressing modes, the difference between program and data space, and the CPU16's internal registers.

Initial stack pointer, program counter, IZ register, and extension register values are fetched from boot ROM. Other CPU resources that must be initialized include the exception vector table and the condition code register. Also, the memory map must be allocated.

4.1.1 The CPU16 Memory Map and Bank Switching

The CPU16 memory map is divided into 16 pages. These pages are called banks. Each bank is 64 Kbytes long for a total of 1 Mbyte of available memory. If the memory is further divided into program and data space, 2 Mbytes are available — 1 Mbyte for program space and 1 Mbyte for data space. However, to accomplish this, the function code pins must be externally decoded.

4.1.1.1 The Memory Map

Assuming combined program and data space, the CPU16 can address 1 Mbyte of memory. Because the MCU has 24 address lines, the memory map begins at address \$000000 and ends at \$FFFFFF. However, when the CPU is driving the address bus, ADDR[23:20] follow the logic state of ADDR19. This means that if the CPU drives ADDR19 high, then ADDR[23:20] will also be high. Likewise, if the CPU drives ADDR19 low, then ADDR[23:20] will also be low. Thus, there is a large gap in the middle of the memory map that the CPU cannot access. This gap begins at \$080000 and ends at \$F7FFFF. **Table 5** illustrates examples of accessible and inaccessible memory.

Table 5 Examples of Accessible and Inaccessible Addresses

Hex Address	A[23:20]	A[19:16]	A[15:12]	A[11:8]	A[7:4]	A[3:0]	Accessible?
\$04000	%0000	0100	0000	0000	0000	0000	yes
\$08000	%0000	1000	0000	0000	0000	0000	no
\$F8000	%1111	1000	0000	0000	0000	0000	yes

The address line comparators used for matches between the address bus and the chip select base address registers (CSBAR) in the system integration module (SIM) still do a comparison on all 24 address lines. As address lines A[23:19] always have the same value, i.e., all high or all low, the address comparators will never find a match between a CSBAR and the physical address bus if a value between \$08000 and \$F7FFFF is in the CSBARx register.

The memory map for combined program and data space is shown in **Figure 17**. As shown in **Figure 17**, the memory map is divided into 16 banks of memory, and each bank is 64 Kbytes long. The most significant nibble of the addresses in banks 0 through 7 is \$0, and the most significant nibble of the addresses in banks 8 through 15 is \$F.

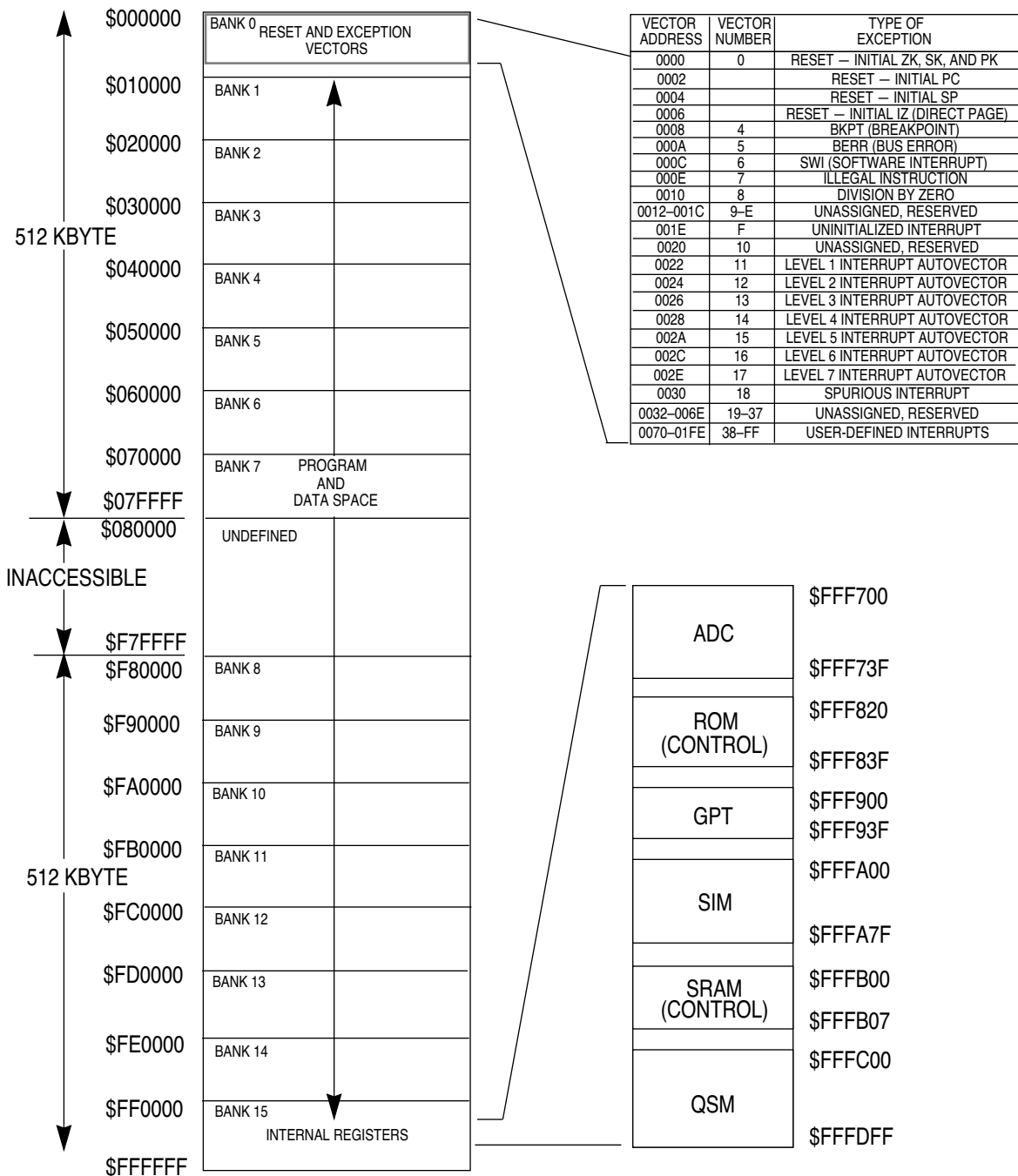


Figure 17 Pseudolinear Addressing with Combined Program and Data Spaces

4.1.1.2 The Extension Fields

The CPU16 generates the lower 20 bits of a 24-bit address by concatenating a 4-bit value in an extension field with a 16-bit address. There are five extension fields: EK, XK, YK, ZK, SK, and PK. The EK field contains ADDR[19:16] of the address used by the extended addressing mode. The XK, YK, and ZK fields contain ADDR[19:16] of the indexed registers IX, IY, and IZ, respectively. Likewise, the SK field extends the stack pointer, and the PK field extends the program counter. Immediately after the release of reset, the ZK, SK, and PK fields are determined by the values stored in the reset vector at location \$000000. All other extension fields must be written by the program code after reset. This is done

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with the transfer B to extension field instructions (TB EK, TBXK, TBYK, TBZK, and TBSK). An example of how to modify an extension register is shown below:

```
INIT:      LDAB  #01
           TB EK      ;EK is now set to $1
ACCESS:    LDD  $0000 ;Load accumulator D with the value at address $10000
```

4.1.1.3 Switching Between Banks

One way to access a particular bank when doing extended addressing is to write that bank number into the EK register. Then, every time the program reads or writes a memory location, bits 16 through 19 of the extended address will be the value in the EK register. Many programmers use the EK register to access bank 15, since that is where the internal registers are located. To access other banks, use one or more of the index registers as page pointers. The IZ register is the most convenient register to use because both it and the ZK field can be stored in the reset vector so that it is initialized automatically out of reset.

Shown below is a short sample code snippet that uses index registers as page pointers. In this example, the IY register points to bank 10, and the EK field points to bank 15. This code snippet initializes CS-BOOT to point to bank 10. Note that the addresses written to the chip select base address registers include bits [23:20]. This is because the address comparators that determine whether a chip select line should assert compare bits [23:20] of the actual address bus to bits [23:20] of the address in the chip select base address register. The chip select registers are discussed in further detail in **4.2.6 Chip-Select Pin Assignment Registers (CSPAR0 and CSPAR1)**.

```
INITSYS:
  LDAB  #0F      ;set EK to $0F to access control registers
  TB EK
  LDAB  #0A      ;IY will address bank 10
  TBYK

CSINIT:
  LDD  #FA03     ;CSBOOT block size=64 KBytes, assume 16-bit port
  STD  CSBARBT   ;base addr = $FA0000, bank A

MAIN:
  LDD  $1234     ;Load D with the immediate value of $1234
  STD  $7300,Y   ;Store $1234 at $FA7300 (bank 10)
```

In summary, the memory map for CPU16-based processors consists of two 512 Kbyte blocks separated by a gap from address \$80000 to address \$F7FFFF. This is because when CPU driven, address lines [20:23] follow the same logic state as address line 19. Because these lines are driven automatically, the CPU only “sees” the lower 20 bits of the address, and the upper 4 bits are transparent. Therefore, the CPU can view the memory space as sixteen continuous 64 Kbyte banks without worrying about the gap between banks 7 and 8 when accessing memory.

4.1.2 Exceptions

An exception is a special condition, such as a reset, an interrupt, or an address error, that pre-empts normal processing. When the processor recognizes an exception, it jumps to a special address and executes code starting at that address until it reaches a return from interrupt (RTI) instruction. Then, it resumes execution of the normal program code. The vectors in the exception vector table tell the processor the starting address of each exception routine.

4.1.3 Exception Vector Table

The CPU16 recognizes 256 exception vector numbers. Each vector number corresponds to a space in the exception vector table that is one word long. Thus, the table extends 512 bytes upward in memory from the base address. Each of the spaces in the table contains a 16-bit value that is used as an address pointer, or vector. The actual address of each of the vectors in the table, referred to as the vector address, is two times the vector number and is located in memory bank 0.

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Table 6 is an overview of the exception vector table. Refer to **SECTION 9 EXCEPTION PROCESSING** in the *CPU16 Reference Manual* (CPU16RM/AD) for detailed discussion of exception processing and a complete list of exception vectors.

The first four words in the exception vector table are used for the initial ZK, SK, and PK values, the initial stack pointer and program counter values, and the initial IZ register value. These are referred to collectively as the reset vector, because the CPU16 loads them during reset exception processing. Unlike other vectors, the reset vector is mapped to program space, to facilitate fetching the values. The reset vector is always located at address \$000000.

All the other exception vectors occupy one word in the table, and are located in data space. These vectors point to the beginning of software routines that handle particular exceptions. All the vectors in the exception vector table must be initialized. The reset vector is generally fetched from external ROM. Correct initial values for the reset vector must be written to addresses \$000000 through \$000006 in order for the system to begin program execution.

Following is an example of how the exception vector table works. An external device asserts $\overline{IRQ7}$, and the CPU acknowledges the interrupt service request. The external device must either provide a user vector number on the data bus and then terminate the bus cycle by asserting \overline{DSACK} , or it must assert \overline{AVEC} and allow the processor to automatically supply the level 7 autovector number, which is \$17. Assuming the external device asserts \overline{AVEC} , vector number \$17 is automatically supplied to the CPU16. The CPU16 multiplies the vector number by two to calculate the vector address, which in this case is \$2E. The CPU reads address \$2E and uses the 16-bit number it contains as the starting address of the interrupt service routine. It does not use the PK register when jumping to exception routines except in the case of the reset vector. All other exception handlers must be located within bank 0, or vectors must point to a jump table.

Table 6 Exception Vector Table

Vector Number (Hexadecimal)	Vector Offset (Hexadecimal)	Assignment
0	0	Reset: Initial ZK, SK, and PK
1	2	Reset: Initial Program Counter
2	4	Reset: Initial Stack Pointer
3	6	Reset: Initial IZ (Direct Page)
4 – 8	8 – 10	Various Errors and Exceptions
9 – E	12 – 1C	Unassigned, Reserved
F	1E	Uninitialized Interrupt
10	20	Unassigned, Reserved
11	22	Level 1 Interrupt Autovector
12	24	Level 2 Interrupt Autovector
13	26	Level 3 Interrupt Autovector
14	28	Level 4 Interrupt Autovector
15	2A	Level 5 Interrupt Autovector
16	2C	Level 6 Interrupt Autovector
17	2E	Level 7 Interrupt Autovector
18	30	Spurious Interrupt
19 – 37	32 – 6E	Unassigned/Reserved
38 – FF	70 – 1FE	User Defined Interrupts

4.1.3.1 Initializing the Reset Vector

Immediately after the release of RESET, an internal state machine fetches the word values at addresses \$000000 through \$000006. These values, generally referred to collectively as the reset vector, are shown in **Table 7**. The values in the reset vector must be initialized in order for program execution to begin.

Table 7 Reset Vector for CPU16

Address	Reset Vector
\$0000	Initial ZK, SK, and PK
\$0002	Initial Program Counter Lower Word
\$0004	Initial Stack Pointer Lower Word
\$0006	Initial IZ Register Lower Word

Sample code to initialize the reset vector follows. Make sure that the stack does not overlap the program code (the stack grows downward in memory). If the assembler does not recognize “DW”, check the manual to determine the format for defining a constant word. Another common format is “DC.W.” This example is in the file “init_res.asm” in the archive “16Z1_init” on the Freeware Data System.

```

org    $0000           ;begin at address $000000 of memory map
DW     $0000           ;initial ZK, SK, and PK = 0
DW     $0200           ;initial PC = $200
DW     $3000           ;initial SP = $3000
DW     $0000           ;initial IZ = $0000

```

4.1.3.2 Initializing Exception Vectors Other Than Reset

Each exception vector should point to a handler routine in case the exception is accidentally taken. In an actual program, the vectors would point to different labels, but in the example below, all of the vectors point to the same label (INT). This label must be included later on in the code in case an exception is taken. This example is in the file “init_res.asm” in the archive “16Z1_init” on the Freeware Data System.

```

org    $0008           ;put the following code in memory after the reset vector.
DW     $0000           ;The address of label INT is stored at location $0008,
DW     INT              ;which is the breakpoint vector
DW     INT              ;Bus Error
DW     INT              ;Software Interrupt
DW     INT              ;Illegal Instruction
DW     INT              ;Division by Zero
.
.
etc.

```

In the actual program code, the following routine must be included:

```

INT    {code to handle}
        {the exception}
        {goes here}
RTI                                ;return to the code that was previously being executed

```

4.1.4 CPU Condition Code Register

The CPU condition code register contains some very important information. The CCR is discussed on page 3-4 of the *CPU16 Reference Manual* (CPU16RM/AD). The field that the user code must initialize is the interrupt priority level field, which consists of bits [7:5]. The interrupt priority level determines which interrupts are recognized and which are masked. Level 7 interrupts are always recognized. To allow other interrupts, this field must contain a value that is lower than the interrupt priority level desired. For example, to allow level 6 interrupts, the value must be %101 or less. Out of reset, the field has a value of %111, which disables all interrupts except for level 7 interrupts.

4.2 Configuring the System Integration Module

Since the SIM determines important operating characteristics of the entire MCU, it should be the first module after the CPU to be initialized. The following paragraphs discuss registers important to initial configuration.

4.2.1 System Integration Module Configuration Register (SIMCR)

The SIMCR controls module mapping for the MCU, internal use of the FREEZE signal, and the precedence of simultaneous interrupt requests of the same priority. Configure the SIMCR as follows.

Leave the state of the module mapping (MM) bit at its reset state of one. MM determines where the internal control registers are located in the system memory map. When MM = 0, register addresses range from \$7FF000 to \$7FFFFFF; when MM = 1, register addresses range from \$FFF000 to \$FFFFFF. However, since the CPU16 cannot access addresses \$080000 to \$7FFFFFF, do not change the MM bit to zero.

1. If using the software watchdog, periodic interrupt timer, or the bus monitor, select action taken when FREEZE is asserted. The freeze software enable (FRZSW) bit determines whether the software watchdog and periodic interrupt timer counters continue to run when FREEZE is asserted, and the freeze bus monitor enable (FRZBM) bit determines whether the bus monitor continues to operate when FREEZE is asserted.
2. Select the interrupt arbitration level for the SIM with the interrupt arbitration (IARB) field. The default state out of reset is \$F, the highest precedence. To avoid spurious interrupts, each module requesting interrupts must have a unique, non-zero value in the IARB field. The CPU treats external interrupt requests as SIM interrupts.

4.2.2 Clock Synthesizer Control Register (SYNCR)

SYNCR controls clock frequency, clock signal usage during low-power stop, and frequency of the 6800 bus clock output (ECLK). Configure SYNCR as follows.

Set frequency control bits (W,X,Y) to specify frequency.

1. Select action to be taken during loss of crystal (RSTEN bit): activate a system reset or operate in limp mode.
2. Select system clock during LPSTOP (STSIM and STEXT bits).
3. If using the ECLK, select the ECLK frequency (EDIV bit).

4.2.3 System Protection Control Register (SYPCR)

SYPCR controls the software watchdog, which is enabled out of reset. This means that, unless the SWE bit is cleared, a program must write the appropriate service sequence to the software service register (SWSR) in a defined period or the MCU will reset each time the watchdog times out.

Disable the software watchdog, if desired, by clearing the SWE bit.

1. If the watchdog is enabled, perform the following actions.
 - A. Choose whether to prescale the software watchdog clock (SWP bit).
 - B. Select the time-out period (SWT bits).
2. Enable the double bus fault monitor, if desired (DATAFE bit or HME bit).
3. Enable the external bus monitor (BME bit) if desired.
4. Select the time-out period for bus monitor (BMT bits).

4.2.4 Periodic Interrupt Timer Register (PITR)

PITR and PICR control the periodic interrupt timer (PIT). The PIT begins to run when a timing modulus is written to the PITM field in PITR. However, interrupt requests from the PIT are recognized only after an interrupt priority level is written into the PIRQL field in the PICR. Clearing PITM stops the timer; clearing PIRQL disables interrupts, but the timer continues to run. Because the CPU treats external interrupts as SIM interrupt requests, PIT interrupts take precedence over external interrupts of the same priority. To use the timer, proceed as follows.

1. Make certain that there is a vector to the interrupt service routine in the exception vector table, and that there is a service routine at the address pointed to.
2. Select whether or not to prescale the timer clock signal (PTP bit in PITR).
3. Select the timing modulus or interrupt rate (PITM field in PITR).

4.2.5 Periodic Interrupt Control Register (PICR)

1. Determine the appropriate PIT vector number and interrupt priority.
2. Write vector number and interrupt priority to PIV and PIRQL fields in PICR.

4.2.6 Chip-Select Pin Assignment Registers (CSPAR0 and CSPAR1)

The chip-select pins can be used in a number of ways. CSPAR determine the functions of the pins.

1. Set up the chip-select pins for discrete output, 8-bit chip-select operation, 16-bit chip-select operation, or alternate function.
2. If a chip-select circuit is used to generate an interrupt acknowledge signal, it must be configured for chip-select operation. However, if a chip-select circuit is used to generate an autovector, the pin can also be used for discrete output or its alternate function.

4.2.7 Chip-Select Base Address Registers (CSBARBT, CSBAR[0:10])

Chip-select signals are asserted when the CPU accesses certain ranges of addresses. The base address registers specify the address ranges for each chip-select circuit.

1. Reprogram the base address and/or blocksize of $\overline{\text{CSBOOT}}$ if desired. The default value out of reset is a base address of \$000000 with a blocksize of 1 Mbyte.
2. Program the base address and block size for each chip-select circuit that is used. The base address must be on a word boundary of the block size. For example, for an 8 Kbyte block size, the base address can be \$2000, \$4000, \$6000, \$8000, etc. If a chip-select circuit is used to generate an interrupt acknowledge signal or an autovector, the base address register must be set to \$FFF8 or higher because interrupt acknowledge cycles occur in CPU space. Remember that the CPU16 cannot access memory locations \$080000 to \$F7FFFF, so do not program these addresses in the base address register.

4.2.8 Chip-Select Option Registers (CSORBT and CSOR[0:10])

The option registers control the conditions under which a chip-select signal is asserted.

1. Reprogram the options for $\overline{\text{CSBOOT}}$ if desired. Reducing the number of wait states from the reset value of 13 increases execution speed.
2. Program the option registers for each chip-select circuit used.
 - A. MODE — Select asynchronous mode (%0) unless using the ECLK output to provide synchronous bus timing for 6800 peripherals. In synchronous mode (%1), the STRB and $\overline{\text{DSACK}}$ fields have no effect.

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- B. BYTE — This field determines whether to assert the chip-select signal for an upper-byte access, lower-byte access, both, or neither. When two 8-bit memories are used to make up one 16-bit port, the associated chip-select circuits are programmed identically except for BYTE field values — select upper byte for one and lower byte for the other.
- C. R/ \overline{W} — This field specifies whether to assert the chip-select signal during a read cycle, a write cycle, or both. When the chip-select circuit is used to generate an IACK signal or to provide an autovector, this field must be set to “read” or “read/write”.
- D. STRB — This field specifies whether chip-select assertion is synchronous with \overline{AS} or \overline{DS} . If a chip-select circuit is used to generate an IACK signal or to provide an autovector, this field should be set to “ \overline{AS} ”.
- E. \overline{DSACK} — This field either specifies the number of wait states to insert before the chip-select circuit asserts \overline{DSACK} and terminates the bus cycle, or it specifies that the external device must provide the \overline{DSACK} signal by driving the external \overline{DSACK} pins. Assertion of the external \overline{DSACK} pins will terminate a bus cycle even if the \overline{DSACK} field is programmed for a certain number of wait states. If a chip-select circuit is used to provide an autovector, fast termination is automatically selected, and the \overline{DSACK} field is not used. For more information on how to determine the number of wait states needed, see **2.9.1 Using Chip-Selects to Generate DSACK**
- F. SPACE — This field indicates the address space of the access. To access memory, select supervisor or supervisor/user space. For IACK cycles, select CPU space.
- G. IPL — If the chip-select circuit is used to provide an IACK signal or \overline{AVEC} , the IPL field indicates the interrupt priority level selected.
- H. \overline{AVEC} — This field determines whether a chip-select circuit generates an autovector in response to an IACK initiated by the assertion of an \overline{IRQ} pin. For normal bus cycles, this field is not used. If a chip-select circuit is to be used to generate an IACK signal, program this field to zero to disable autovector generation. If a chip-select is to be used to generate an autovector, program this field to one.

4.2.9 General-Purpose I/O Ports

Certain SIM pins can be configured as general-purpose I/O ports when not used for other purposes. Port E pins share function with bus-control signals, port F pins share function with interrupt request signals, and port C (output only) pins share functions with chip-select signals. The ports are controlled by pin assignment registers (CSPAR, PEPAR, and PFPAR) and data direction registers (DDRE and DDRF). Pin assignment registers determine whether a pin is used for general-purpose I/O or for another function. Data direction registers determine whether an I/O pin is an input or an output. Data is written to and read from the port data registers (PORTC, PORTE and PORTF).

1. Assign port pins by writing to pin assignment registers.
2. Program the data direction registers to assign input or output function to port pins.
3. Use the Port data registers to read/write data.

4.2.10 Example of SIM Initialization

This example assumes that three other files, equates.asm, init_res.asm and init_int.asm, exist. The file equates.asm defines labels for the internal registers. The file init_res.asm initializes the reset vector. It contains the code shown in **4.1.3.1 Initializing the Reset Vector**. The file init_int.asm initializes the interrupt vectors. It contains the code shown in **4.1.3.2 Initializing Exception Vectors Other Than Reset**. This file is not necessary for debugging, but should be included in final application code. This example can be assembled with the IASM16 assembler available from P&E Microcomputer Systems. This example is in the file “init_res.asm” in the archive “sim_init” on the Freeware Data System.

This example initializes chip selects 0, 1, and 2 to select two 8-bit external RAMs. The RAMs are mapped at address \$30000. It also initializes the periodic interrupt timer to time out every one second.

```
INCLUDE 'equates.asm' ;include register equates
```

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```
INCLUDE 'init_res.asm' ;initialize reset vector
INCLUDE 'init_int.asm' ;initialize exception table

ORG      $200          ;begin program at $200, immediately after
                       ;the exception table

INITSYS:
LDAB     #$0F          ;point to internal registers
TBEB
LDAB     #$03
TBXK     ;point XK to bank 3 for external RAM access
LDX      #$0000        ;now X points to $30000
LDAA     #$7F
STAA     SYNCR         ;set system clock to 16.78 MHz
CLRA
STAA     SYPCR         ;disable software watchdog
LDD      MCR
ANDD     #$FFF0        ;set interrupt arbitration field to a
ORD       #$0005        ;unique value.
STD      MCR

INITCS:
* This section initializes two 32K x 8 RAM chips using the Chip Selects. The
* memory will start at address $30000 and will be both byte and word readable
* and writable. This program assumes that the RAM chips have access times of
* 85 ns and require no wait states. The DSACK field of the CSOR Registers may
* need to be adjusted for chips that have faster or slower access times.
* The hardware configuration should be similar to Figure 13b shown earlier
* in this tutorial in the section "Connecting Memory and Peripherals." However,
* if loading this program into memory using a debugger, connect CSBOOT to
* RAM instead of ROM.

*****
LDD      #$0003
STD      CSBARBT        ;base address of $00000, block size of 64K
LDD      #$7870
STD      CSORBT         ;both bytes, R/W, one wait state (if you
                       ;are programming this code into ROM, set
                       ;this field to $6B30).

* Set up chip selects with a base address of $30000, block size of 64K

LDD      #$0303
STD      CSBAR0         ;set CS0 base addr to $30000, 64K blk
LDD      #$0303
STD      CSBAR1         ;set CS1 RAM base addr to $30000, 64K blk
STD      CSBAR2         ;set Chip Select 2 at base addr $30000
LDD      #$5030
STD      CSOR0         ;set Chip Select 0, upper byte, write only
LDD      #$3030
STD      CSOR1         ;set Chip Select 1, lower byte, write only
LDD      #$6830
STD      CSOR2         ;set Chip Select 2, both bytes, read only
LDD      #$3FFF
STD      CSPAR0        ;set Chip Selects 0,1,2 to 16-bit ports
CLRW     $0000,X       ;write 0 to $30000

INIT_PIT:

* This section of code initializes the periodic interrupt timer to interrupt
* every second, assuming a 32 kHz input to EXTAL.

LDD      #CLKINT
STD      $0080,Z       ;store starting addr of interrupt routine
                       ;at location $80 ($40 X 2). Z was
                       ;initialized to 0 in "init_res.asm".

LDD      #$0640
STD      PICR          ;interrupt level 6, vector $40
LDD      #$0110
STD      PISR          ;time-out period of 1 second
ANDP     #$FF1F        ;mask interrupts below level 6
ORP      #$00A0

ITSELF
BRA     ITSELF         ;stay here while waiting for interrupts

CLKINT
;interrupt routine for PIT
```

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```
INCW      $0000,X      ;increments the first word in the RAM at
RTI                               ;address $30000

INT
RTI                               ;unused interrupts point here
```

4.3 Configuring Internal RAM

The internal RAM can be mapped to any 2 Kbyte boundary in the address map, but it must not overlap the module control registers or be mapped to addresses \$80000 to \$7FFFFFFF which are inaccessible to the CPU16. The RAM is in low power stop mode out of reset. To initialize the RAM, write the desired base address to the RAM base address and status register (a write-once only register) and clear the STOP bit to enable the RAM.

If battery backup for the RAM is not used, connect the V_{STBY} pin to ground. When using the ICD16 debugger, make sure not to display any potentially uninitialized memory in the F3 and F6 windows, because the debugger tries to read this memory and will display error messages if it is uninitialized.

4.4 Configuring the Queued Serial Module

The queued serial module (QSM) is divided into two submodules: the serial communications interface (SCI) and the queued serial peripheral interface (QSPI). The following sections give basic examples of QSM configuration. See the *QSM Reference Manual* (QSMRM/AD) for more detailed information.

4.4.1 Configuring the SCI

The following example program can be assembled with IASM16. This example is in the “sci_init.asm” file in the archive “16Z1_init” on the Freeware Data System. The program prints a five-character message to the screen. Do the following before running this program:

1. Connect an RS-232 cable from the PC serial port to the target board.
2. When using ICD16, set the serial communications protocol for the COM port being used, 9600 baud, no parity, eight data bits, and one stop bit. For example, when using COM 2, type in the command: serial 2 9600 n 8 1
3. When using ICD16, enable the serial communications by typing: serial on
4. Load and run the program.

* SCI INITIALIZATION: This program initializes the SCI and prints the message
* “12345” to a dumb terminal.

```
INCLUDE      'EQUATES.ASM'      ;EQUates for common register addresses
INCLUDE      'INIT_RES.ASM'      ;initialize reset vector
INCLUDE      'INIT_INT.ASM'      ;initialize interrupt vectors

ORG          $200                ;begin program at $200, immediately after
                                ;the exception table

INIT_SIM
LDAB #0F                ;point to bank $F for internal register addressing
TBEK
CLRB
TBXK
LDAA #7F                ;increase clock speed
STAA SYNCR              ;disable software watchdog
CLR SYPCR

INIT_SCI
LDD #0037
STD SCCR0                ;set the SCI baud rate to 9600
LDD #000C
STD SCCR1                ;enable the receiver and transmitter

PRINT
LDX #MESSAGE             ;load the address of the message
                                ;to be printed into address register X.
```

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```
LDE #0005          ;counter that will count to end of message
```

```
* The next three commands check to see if the transmit data register is empty
* by looking at the TDRE bit in the SCI status register (SCSR).  If the TDRE bit
* is zero, then there is data in register TDR that has not yet been sent to the
* transmit serial shifter.  If the TDRE bit is one, then the transfer has
* occurred, and a new character may be written to register TDR.  Thus, this
* sequence of code loops until the TDRE bit is one.
```

```
LOOP    LDAB    0,X          ;1st char in accumulator B
CHAR    LDAA    SCSR         ;see if TDRE bit in SCI Status Register is
        ANDA    #$01        ;set
        BEQ     CHAR         ;wait until it is
        LDAA    SCSR
        ANDA    #$FE
        STAA   SCSR         ;clear TDRE bit
        CLRA
        STD    SCDR         ;store char to be printed in data register
        AIX    #1          ;point to next char
        SUBE   #$01
        BNE    LOOP        ;loop to print next char
FINISH  BRA     FINISH      ;stay here when done

INT
MESSAGE RTI                ;unused exceptions point here
        FCB    '12345'     ;"12345" will be printed
```

4.4.2 Configuring the QSPI

The QSPI uses a synchronous serial bus to communicate with external peripherals and other MCUs. The QSPI serial protocol is compatible with the serial peripheral interface (SPI) on the M68HC11 and M68HC05 families of MCUs. The module also has a queue, programmable queue pointers that allow up to 16 automatic transfers, and a wrap-around mode that allows continuous transfers to and from the queue with no CPU intervention. The queue is useful in applications such as control of an A/D converter. Remember the following points when using the QSPI:

- Setting the SPE bit to enable the QSPI should be the last step in initialization.
- Data direction register DDRQS and port data register PORTQS must be initialized, even for pins that are assigned to the QSPI in pin assignment register PQSPAR.
- Peripheral chip-select signals are asserted when a command in command RAM is executed, but the assertion state (active high or active low) of the peripheral chip-select signal is determined by the value of the appropriate bit in PORTQS.
- Take special care when writing PORTQS since a read of this register returns the actual pin state and not the data just written to it. Beware of the following scenario:

The QSPI is inactive, and the current value of PORTQS is \$FF. The user software wishes to clear bit 0 and then OR this bit with a value in another register, which also happens to be zero. Thus, the end result should be \$FE. To accomplish this, the software does a BCLR instruction immediately followed by an OR instruction. However, there is a good probability that after the BCLR instruction, the pin state will not have changed by the time the CPU reads PORTQS for the OR instruction. Thus, the CPU could read the value \$FF from PORTQS instead of \$FE and end up with the wrong result. To avoid this scenario, put a NOP or a different instruction between two read-modify-write instructions involving the PORTQS register.

- Take special care when writing PORTQS while using the QSPI because control of the PORTQS pins is shared by the QSPI and the CPU. During transfers, the QSPI controls the pins assigned to it in the PQSPAR, but when transfers are complete, control reverts to what the CPU has written in PORTQS. Beware of the following scenario:

The CPU writes the initial value of PORTQS to \$FF, so that the inactive state of each QSPI chip select pin is high. The CPU configures the active state of each chip select to be low in the command RAM. Later, the user software decides to make PCS1 (bit 4 in PORTQS) drive low all of the time. To do this, it arbitrarily does an AND of PORTQS with \$EF to clear bit 4 without affecting any other bits in the

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register. However, if this is done arbitrarily, there is a possibility that the QSPI will be active and will be driving all of the chip selects low. Thus, the CPU could read bits [3:6] as zero instead of one and end up writing back an erroneous value to PQSPAR. In this situation, all of the chip selects would drive low all of the time. To avoid this scenario, only modify PORTQS when the QSPI is disabled (the SPE bit is zero).

4.4.2.1 QSPI Initialization Example

This example illustrates how to initialize the QSPI in the wrap-around mode, with eight data bits per transfer and active-low peripheral chip-select pins. Modifying the code to disable the wrap-around mode is very simple. The modification is explained in the comments.

This example is in the file “qspiinit.asm” in the archive “16Z1_init” on the Freeware Data System.

```
INCLUDE      'EQUATES.ASM'      ;file of register equates
INCLUDE      'INIT_RES.ASM'      ;initialize reset vector
INCLUDE      'INIT_INT.ASM'      ;initialize interrupt vectors

ORG $200          ;begin program at $200 after the exception table
INIT_SIM:
LDAB #$0F          ;initialize K registers: YK,ZK to bank $F, XK to bank 0
TBEK
TBYK
TBZK
CLRB
TBXK
LDAA #$7F
STAA SYNCR          ;increase clock speed
CLR SYPCR          ;disable software watchdog

INIT_QSPI:
LDD SPCR1
ANDD #$7F
STD SPCR1          ;Clear the SPE bit to disable the QSPI. Enabling the
                  ;QSPI is the last step in the initialization sequence.

* The next commands read and clear the flags in SPSR. These flags are the
* QSPI finished flag (SPIF), the mode fault flag (MODF), and the halt
* acknowledge flag (HALTA). The SPIF bit is usually the flag of interest. It is
* set by the QSPI upon completion of a serial transfer when the address of the
* command being executed matches the ENDQP. If wrap-around mode is enabled, the
* SPIF bit is set each time the QSPI cycles through the queue. If interrupts
* are enabled, assertion of the SPIF bit causes an interrupt.

LDAB SPSR
ANDB #$00
STAB SPSR          ;read and clear flags in SPSR

* The next command defines the initial states of the chip select signals in PORTQS
* (formerly called QPDR).
* The chip selects may be active high or active low. The initial state set in
* the PORTQS is the inactive state. The active state is selected in the command RAM
* In this example, the initial state of the chip
* select lines is high, and the initial state of SCK is low. This defines the
* chip selects to be active low and SCK to be active high. The SCI TXD signal
* bit is not affected.

LDAB #$7B
STAB PORTQS          ;define initial states of chip selects/SCK
STAB PQSPAR          ;Assign all pins to the QSPI. Pins can be
                    ;assigned to the QSPI or for general
                    ;purpose I/O on a pin by pin basis.

LDAB #$7E
STAB DDRQS          ;Select the direction of the signal lines
                    ;as outputs, except for MISO.

LDD #$8002
STD SPCR0          ;Configure the QSPI as master, select
                    ;8 data bits per transfer, set the inactive
                    ;state of SCK as low, capture data on the
                    ;leading edge of SCK, baud rate is 4.19 MHz
```

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* The next commands set the control parameters. Interrupts are not enabled. To enable interrupts upon assertion of the SPIF bit, set SPCR2[15]. To clear an interrupt, read and then clear the SPIF bit. Wrap-around mode is enabled. NEWQP is set to zero, and ENDQP is set to \$F. Thus, the QSPI will continuously transmit the data between \$0 and \$F in the queue. To disable wrap-around mode so that the QSPI only goes through the queue once, clear the WREN bit (SPCR2[14]) to a zero.

```
LDD #$4F00
STD SPCR2           ;NEWQP=0, ENDQP=$F, WREN is enabled
STAB SPCR3         ;Disable loop mode, HALTA and MODF
                  ;interrupts, and HALT.
LDX #DATA          ;Point X to the data to be transmitted.
LDY #TR0           ;Point Y to the transmit data RAM.
LDZ #CR0           ;Point Z to the command RAM
LDE #$10           ;Set a counter to count down from 16 ($10),
                  ;since there are 16 queue entries to fill.
LOOP: LDD 0,X
      STD 0,Y       ;Begin a loop to fill the transmit RAM.
      AIX #$02      ;Store the data right-justified.
      AIY #$02
```

* The next commands fill the command RAM in a right-justified manner. There is one byte of control information for each QSPI command to be executed in the queue. Here, all four chip selects will drive low during each serial transfer.

```
CLRB
STAB 0,Z
INCZ           ;fill command RAM: chip selects active low
SUBE #$01     ;Subtract one from the counter
BNE LOOP      ;Fill next queue entry if not done
LDD #$8000
STD SPCR1     ;Begin operation by setting the SPE bit.
FINISH: BRA FINISH ;Normally, this would begin the next task.
INT: RTI ;unused interrupts will jump here
DATA DB 16 ;Set aside memory space for the data to be
           ;transmitted. This program does not
           ;initialize the data.
```

4.4.3 Initializing QSM Interrupts

To enable interrupts on the QSM, initialize the following five fields:

1. ILPQSPI and ILSCI in the QILR register determine the priority levels of QSPI and SCI interrupts, respectively. If the fields are set to the same level, the QSPI takes priority.
2. INTV[7:0] in the QIVR register determines the interrupt vector number. For the QSPI, the least significant bit is read as a one, and for the SCI, the least significant bit is read as a zero.
3. IARB in the QMCR register determines precedence if the QSM and another module simultaneously make an interrupt service request of the same priority. This field must be initialized to a unique, non-zero value if interrupts are enabled.
4. IPL in the CPU condition code register determines the priority level at which interrupts are recognized. In order for QSM interrupts to be recognized, this field must be given a value that is lower than the interrupt priority level specified in the QILR register.
5. The interrupt vector tells the processor where to find the interrupt service routine. Store the starting address of the service routine in the interrupt vector table at the appropriate vector offset address. The vector offset address is equal to (interrupt vector number X 2).

4.5 Configuring the General-Purpose Timer

The general-purpose timer (GPT) is a software-interrupt driven timer that is very similar to the timer

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used extensively on the M68HC11 series of microcontrollers. Because the GPT uses design rules for the M68300 family, the GPT runs four times faster on the M68300/M68HC16 families than it does on the M68HC11 family. While the GPT does reside on the intermodule bus, it does not have a self-contained arithmetic logic unit or RISC-like microengine (like the time processor unit on other modular MCUs) with specialized instruction sets. The GPT functions are briefly described below. For a more detailed explanation, refer to the *GPT Reference Manual* (GPTRM/AD).

Input Capture Pins (IC[1:3]): Each of these pins is associated with a single input capture function and has a dedicated 16-bit capture register to hold the captured counter value. These pins can also be configured for general-purpose I/O.

Output Compare Pins (OC[1:4]): Each of these pins has a dedicated 16-bit compare register and a 16-bit comparator. Pins OC2, OC3, and OC4 are associated with a specific output compare function, whereas the OC1 function can affect the output of any combination of output compare pins. Automatic preprogrammed pin actions occur on a successful match. The OC1 pin can alternately be used to output the clock selected for the timer counter register (TCNT). Also, any of the pins can be used for general-purpose I/O.

Pulse Accumulator Input Pin (PAI): The pulse accumulator counter (PACNT) is an 8-bit read/write up counter register that can operate in an external event counting or gated time accumulation mode. The user software can write the number of edges to be counted to the PACNT register. As the edges are counted, the counter will approach \$FF, roll over to \$00, and generate an interrupt. The pulse accumulator overflow flag will indicate that the count has rolled over.

Pulse-Width Modulation (PWMA, PWMB): These are the outputs to the two PWM functions. They can be programmed to generate a periodic waveform with a variable frequency and duty cycle. Alternately, these pins can be used for general-purpose I/O. PWMA can also be used to output the clock selected as the input to the PWM counter (PWMCNT).

Auxiliary Timer Clock Input (PCLK): This is an external clock input dedicated to the GPT that can be used as the clock source for the capture/compare unit or the PWM unit in place of one of the prescaler outputs. If this pin is not used as a clock input, it can be used as a general-purpose input pin.

General-Purpose I/O: Many of the GPT pins can be used as general-purpose I/O. All that is needed to configure a pin to general purpose I/O is to select the data direction in the data direction register (called PDDR in older manuals and DDRGP in newer manuals) and the actual data in the data register (called PDR in older manuals and PORTGP in newer manuals). Take special care when writing data to the data register, since a read of this register returns the actual pin state and not the data just written to it. Beware of the following scenario:

The current value of PORTGP is \$FF. The user software wishes to clear bit 0 and then OR this bit with a value in another register, which also happens to be zero. Thus, the end result should be \$FE. To accomplish this, the software does a BCLR instruction immediately followed by an OR instruction. However, there is a good probability that after the BCLR instruction, the pin state will not have changed by the time the CPU reads PORTGP again for the OR instruction. Thus, the CPU could read the value \$FF from PORTGP instead of \$FE and end up with the wrong result. To avoid this scenario, put a NOP or a different instruction between two read-modify-write instructions involving the PORTGP register.

4.5.1 GPT Interrupts

Several steps must be followed in order for a GPT channel to request interrupt service.

1. Store the starting address of the interrupt service routine in the CPU interrupt vector table.

The location in the vector table where the service routine starting address is stored is called the vector address. The vector address is calculated from the interrupt vector number — the address is two times the vector number.

The interrupt vector number is formed by concatenating a base vector number with the vector

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number given in Table 7-1 on page 7-3 in the *GPT Reference Manual* (GPTRM/AD). As shown in Table 7-1, each timer channel has a separate vector number. Choose a base vector number and write it to bits [7:4] in the GPT interrupt configuration register (ICR). For example, choosing a base vector number of \$81 would assign interrupt vector \$80 to input capture 1, interrupt vector \$82 to input capture 2, interrupt vector \$83 to input capture 3, and so on, through assignment of interrupt vector \$8B to pulse accumulator input flag.

For example, if output compare 1 is being set up to request interrupt service, the interrupt vector is \$84. The vector address is:

$$2 * \$84 = \$108$$

Thus, the starting address of the interrupt routine must be stored in location \$108.

2. Store an interrupt priority level for the GPT in bits [10:8] of the ICR.

This value determines the priority of GPT interrupt service requests. The value must be a number between 1 and 7 — level 7 has the highest priority, and level 1 has the lowest. The value stored in the IPL field in the CPU condition code register determines whether an interrupt request is recognized. The value in the IPL field must be lower than the GPT interrupt priority level in order for the GPT to interrupt the CPU, unless the interrupt level is seven, in which case it cannot be masked.

3. If desired, specify which interrupt source within the GPT has the highest priority by writing to bits [15:12] of the ICR.

This value determines which interrupt source within the GPT has the highest priority. As Table 7-1 on page 7-3 in the *GPT Reference Manual* (GPTRM/AD) shows, each interrupt source within the GPT is pre-assigned a priority. However, the user can pick one of those sources to have the highest priority. For example, if a \$4 is written to bits [15:12] of the ICR, then OC1 will have the highest priority. When OC1 generates an interrupt, the low nibble of the vector will be \$0 instead of \$4. The remaining channels maintain their original relative priority and vector addresses.

4. Store an interrupt arbitration value in the IARB field of the GPT module configuration register.

The IARB field value determines precedence when the CPU receives more than one interrupt request of the same interrupt priority level. Each interrupting module must be assigned a unique IARB number between \$01 (lowest precedence) and \$0F (highest precedence).

5. Set the interrupt enable bit for the channel in the timer interrupt mask register (TMSK1/TMSK2). This simply involves writing the channel's bit number to a one.

To clear an interrupt, negate the appropriate interrupt status flag in the timer interrupt flag registers (TFLG1/TFLG2). Read the flag in the asserted state and then write a zero to the bit. As long as the interrupt status flag is set, the channel will continue to request interrupts.

4.5.2 GPT Initialization Example

The following example uses all five output compare channels. In this example, OC1 controls the OC1, OC2, and OC3 pins. OC4 and OC5 operate independently. The period of OC[1:3] is \$200 TCNTs. The period of OC4 is \$400, and the period of OC5 is \$800. The frequency of TCNT is the system clock divided by four. Therefore, for a 16.778 MHz system clock, each TCNT tick is 238 ns long. Thus, the period of OC[1:3] is approximately 122 μ s, and the periods of OC4 and OC5 are approximately 244 μ s and 488 μ s, respectively.

This example is in the file "gpt_init.asm" in the archive "16Z1_init" on the Freeware Data System.

```
INCLUDE      'EQUATES.ASM'      ;register addresses
INCLUDE      'INIT_RES.ASM'     ;initialize reset vector
INCLUDE      'INIT_INT.ASM'     ;initialize interrupt vectors
ORG          $200
```

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```
INIT_SIM:
    LDAB    #$0F                ;set EK to $F to point to internal regs
    TBEB
    LDAA    #$7F                ;increase clock speed to 16.778 MHz,
    STAA    SYNCR               ;assuming a 32 kHz crystal and using the VCO
    CLR     SYPCR               ;disable software watchdog
    ANDP    #$FF1F
    ORP     #$00A0              ;allow interrupts on levels 6 and 7
```

```
INIT_GPT:
    LDD     #$FF00
    STD     PDDR                ;make all GPT pins outputs
    LDD     #$0000              ;set I4/O5 pins to output compare
    STD     PACTL               ;(this is the default value)
    LDD     #$3800              ;set up value for OC1M/OC1D: OC1 controls
    STD     OC1M                ;OC1-3, data = 0 at match
```

* TOC1 works differently than the other four OC channels because it can
* control all five OC channels. Here, it is configured to affect only the
* OC1 - OC3 channels. OC1 does not have the ability to toggle on a match.

```
    LDD     TCNT                ;add offset to TCNT for delay before
    ADDD    #$200               ;first compare
    STD     TOC1                ;store TCNT + Offset into TOC1
    STD     TOC4                ;store TCNT + Offset into TOC4
    STD     TI405               ;store TCNT + Offset into TOC5
```

* All of the OC channels are initialized with the same value so that
* the 5 square waves will be phase locked. Different offsets could be used
* for each channel. This would simply skew the square waves with respect
* to each other; they would still be frequency locked.

```
    LDD     #$5000
    STD     TCTL1               ;OC 4 and 5 will toggle on compare
```

```
INIT_INTS:
    LDD     #OC1_INT            ;Store interrupt routine addresses
    STD     $108,Z              ;in the vector table (Note: this could
    LDD     #OC4_INT            ;be done in the file "init_int.asm".)
    STD     $10E,Z
    LDD     #OC5_INT
    STD     $110,Z
    LDD     #$0085
    STD     GPTMCR              ;set SUPV = 1, IARB = 5
    LDD     #$0680              ;GPT priority = 6, base vector = $80
    STD     ICR
    LDD     #$C800              ;TCNT is Sys CLk Div 4 (reset value)
    STD     TMSK1               ;each count = 238 nsec for 16.78 MHz Sys Clk
                                ;enable interrupts for OC channels
```

```
WAI_FOR_INT
    BRA     WAI_FOR_INT        ;normally, this would go on to the next
                                ;program task
```

* Each time that a match occurs between OC4 or OC5 and the Timer
* Counter (TCNT), the respective OC channel will toggle. If the software
* driver for the OC channel does not service an OC flag for some reason,
* a match will occur each 65,535 TCNT counts. OC1 is a special case. When
* it matches with TCNT, it will drive pins OC1-3 to the level written to
* the respective bits in the OC1D register.

* Following are the interrupt routines. In each one, a new future value
* is written into the appropriate TOC register.

```
OC5_INT:                ;interrupt routine for OC5
    LDD     TI405
    ADDD    #$400
    STD     TI405              ;add #$400 to value in OC5 register
    BCLRW   TFLG1 $8000       ;clear I405 flag
    RTI
```

```
OC4_INT:                ;interrupt routine for OC4
    LDD     TOC4
    ADDD    #$200
    STD     TOC4              ;add #$200 to value in OC4 register
```

```

BCLRW   TFLG1 $4000      ;clear TOC4 flag
RTI

OC1_INT:
LDAB    OC1D              ;interrupt routine for OC1
BNE     DRIVE_PINS_LO    ;branch if pins are high
BSETW   OC1M $0038       ;set OC1-3 to go high at next match
BRA     GET_TOC1
DRIVE_PINS_LO:
BCLRW   OC1M $0038       ;set OC1-3 to go low at next match
GET_TOC1:
LDD     TOC1
ADDD   #$100
STD     TOC1              ;add #$100 to value in OC1 register
BCLRW   TFLG1 $0800     ;clear TOC1 flag
RTI

INT:
RTI              ;unused interrupts point here

```

4.6 Configuring the Analog-to-Digital Converter

The analog-to-digital converter (ADC) takes an analog voltage as an input, and provides a digital reading. It has eight channels and selectable 8- or 10-bit resolution. Each result is available in three formats: right-justified unsigned, left-justified signed, and left-justified unsigned, depending on the address from which it is read. The ADC can also be used for digital I/O. Port ADA is an input-only port, and port ADB is an output-only port. Data in these two ports resides in the port data register (called PDR in older manuals and PORTADA in newer manuals).

In order to use the ADC as an analog-to-digital converter, the user must be sure to properly connect the following pins:

V_{RH} and V_{RL} : These are the analog reference voltages that are connected to the analog reference pins. The ADC uses them as a reference to determine the range of voltage it can expect on the analog input pins. Because they are separated from the analog power supply pins (V_{DDA} and V_{SSA}), they can (and should) be connected to regulated and filtered supplies to allow the ADC to achieve its highest degree of accuracy. Any noise on these two pins will translate into errors in the conversion results. The use of bypass capacitors or low-pass filtering is recommended. In addition, V_{RH} must be less than or equal to V_{DDA} , and V_{RL} must be greater than or equal to V_{SSA} .

V_{DDA} and V_{SSA} : These pins supply power to the analog circuitry associated with the sample amplifier and RC DAC array. Other circuitry in the ADC is powered from the digital power bus (pins V_{DDI} and V_{SSI}). Dedicated power for the RC DAC array is necessary to isolate sensitive analog circuitry from noise on the digital power bus. The power to V_{DDA} and V_{SSA} should be as quiet as possible.

Analog input pins (AN[0:7]): These are the actual input pins to the converter. The input to these pins must be within the range specified by V_{RH} and V_{RL} . The ADC converts the analog input on these pins to digital data. These inputs should have low AC impedance at the pins. This can be accomplished by placing a capacitor with good high frequency characteristics at the input pin. A series resistor can also be used to implement a simple RC filter. However, when using a series resistor, the user must consider the source impedance of the circuit supply the analog signal and any leakage that may occur.

It is imperative that for greatest accuracy in conversions, the analog power supply and reference voltages must be isolated from the digital power bus. There must be low impedance paths between all analog ground points in the circuit. Use large-width PC board traces for routing power to decrease impedance between analog reference points, increase the effectiveness of decoupling/filtering, and decrease the chance of high frequency cross-coupling. For best results, carve an analog ground plane out of the digital ground plane. Chapter 6 of the *ADC Reference Manual* (ADCRM/AD) has more information on pin connection considerations.

4.6.1 ADC Initialization Example

This program initializes the ADC and samples the AD0 pin. It uses the single-channel four conversion sequence. The most recent conversion will be in the E register, and its format will be right-justified unsigned. Be sure to connect V_{DDA} , V_{SSA} , V_{RH} , and V_{RL} as described above in **4.6 Configuring the Analog-to-Digital Converter**. Connect an input signal to the AD0 pin. Make sure that the input is within the range of V_{RH} and V_{RL} .

This example is in the file "adc_init.asm" in the archive "16Z1_init" on the Freeware Data System.

```

INCLUDE 'EQUATES.ASM' ;register equates
INCLUDE 'INIT_RES.ASM' ;initialize reset vector
INCLUDE 'INIT_INT.ASM' ;initialize interrupt vectors
ORG      $200
CLRE

INIT_SIM:
LDAB     #$0F           ;set K fields to $F to point to internal regs
TBK
LDAA     #$7F
STAA     SYNCR          ;increase clock speed
CLR      SYPCR          ;disable software watchdog

INIT_ADC:
LDD      #$0000
STD      ADCMCR         ;enable ADC
LDD      #$0043        ;STS field = 8 A/D clocks
STD      ADCTL0        ;8-bit, sample period=SYS CLOCK/8

START_ADC:
LDD      #$0000
STD      ADCTL1        ;single 4 conversion, single channel, AD0
                        ;writing to the ADCTL1 reg starts conversion
LDAA     #$80

SEE_IF_DONE:
BITA     ADSTAT         ;check for the Sequence Complete Flag
BEQ      SEE_IF_DONE   ;wait until conversion is complete
LDE      RJURRO        ;read result in lower byte of register
BRA      START_ADC     ;go get another sample

INT
RTI      ;unused interrupts point here

```

5 Troubleshooting

Because of the complexity of the MCU, there are a considerable number of potential 'fatal flaws' that can cause a prototype application to either not operate from power up or to fail soon after. This section covers common problems, causes, and fixes. This is not an exhaustive discussion, but it is intended to be used as a check list of the main problem areas that can cause an application to fail.

5.1 Critical Signals to Check

- $\overline{\text{RESET}}$ should stay low for at least 512 clocks during a power-on reset. If using the internal PLL, $\overline{\text{RESET}}$ will remain low for a little longer because the VCO must lock first. $\overline{\text{RESET}}$ should then go high and remain high.
- CLKOUT should be at the system clock frequency. If MODLCK is held high at the release of reset, CLKOUT should be 512 times the frequency going into EXTAL (8.389 MHz for a 32.768 kHz crystal). Make sure that the frequency is exact, as a measurable error may indicate limp mode and oscillator faults. If MODCLK is held low at the release of reset, the frequency on CLKOUT should be the frequency going into EXTAL.
- Immediately after reset, $\overline{\text{CSBOOT}}$ should pulse low five times for a 16-bit port and nine times for an 8-bit port.
- FREEZE should be low and $\overline{\text{HALT}}$ should be high. Otherwise, the MCU is halted, or is in BDM.

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- $\overline{\text{BR}}$ and $\overline{\text{BGACK}}$ should be high. Otherwise, the external bus is granted away.
- Make sure that the data bus pins are configured correctly during reset.
- Make sure that $\overline{\text{IRQ7}}$ is high during reset.

5.2 Common Problems and Solutions

5.2.1 Problem: Device Stays in Reset

1. There is no pull-up resistor on $\overline{\text{RESET}}$. $\overline{\text{RESET}}$ needs an 820 Ω resistor to 5 volts. See **2.1 Using Data Bus Pins to Configure the MCU** and **2.3 Pins that Need Pull-Up Resistors**.
2. A capacitor on $\overline{\text{RESET}}$ can also prevent the device from coming out of reset. Do not put any capacitors on $\overline{\text{RESET}}$. See Sections 2.1 and 2.3.
3. MODCLK is pulled high at the release of $\overline{\text{RESET}}$, and the VCO is not locking. Check the components in the crystal circuit to ensure that they are correct. Check the layout to ensure that the board is clean and that there are no noisy signals nearby to affect operation of the oscillator, and make sure that power is applied to V_{DDSYN} . Also, make sure that the crystal frequency is within specifications. If all else fails, change crystals. See **2.5 Clock Circuitry**.
4. MODCLK is pulled low at the release of $\overline{\text{RESET}}$, and there is no external clock signal. Make sure that there is a signal going into EXTAL. See **2.5 Clock Circuitry**.

5.2.2 Problem: Device Resets Every 16 ms

1. The software watchdog is enabled but is not being serviced by the program. When the watchdog is enabled, the program must write a sequence to the software service register to prevent the watchdog from timing out and resetting the MCU. The software watchdog is enabled out of reset, and the program must disable it by clearing the SWE bit in the SYPCR register. Note that this is a write-once only register.
2. If the code does disable the watchdog, but the device is still resetting every 16 ms, then the code is probably not being executed. Either the memory is not programmed properly, or something is preventing the MCU from executing code. Check all pull-up resistors for good connections and correct values. Also check the frequency of CLKOUT.

5.2.3 Problem: CLKOUT Frequency is Incorrect

1. MODCLK is not driven correctly during reset. To use a crystal and the internal PLL, MODCLK must be driven high during reset. To use an external clock and bypass the internal PLL, MODCLK must be driven low during reset.
2. The crystal is settling into overtones due to a poor quality crystal or incorrect components in the crystal circuit.
3. If the frequency is unstable, it is possible that the crystal is being overdriven. Increase R_s to reduce crystal drive.
4. There is residue on the PCB. Since low frequency crystal circuits tend to be very high impedance, the PCB must be clean, dry, and free of conductive material such as solder rosin and excessive moisture from high humidity.
5. In the absence of other circuit problems, the series resistor is the most probable culprit when an oscillator will not start. The resistor limits the power that starts the crystal oscillating. If the resistance is too low, the crystal will start oscillating in unpredictable modes and could even become damaged. If the resistance is too high, the oscillator will start very slowly or not at all.

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6. If the value of the series resistor is correct, check for the presence of metastable states during power-up. If there is extremely high frequency oscillation on the CLKOUT pin during the first few hundred milliseconds of operation, and increasing the size of R_s does not fix the problem, the only real solution is to find a different brand and/or style of crystal. There is no practical way to compensate for a crystal that exhibits poor self-suppression of the first overtone and first harmonic. Once again, if a particular crystal type and brand is prone to starting at overtones or harmonics, just don't use it. No amount of circuit design will ever compensate for a bad or poor quality crystal.

Usually, it is impossible to observe oscillator operation with an oscilloscope connected to one of the oscillator pins. The oscilloscope adds 3-30 pF and 1-10 M Ω of loading to V_{SS} , which will usually affect oscillator operation. When the oscilloscope is connected to the EXTAL input, the 10 M Ω to V_{SS} (oscilloscope input) forms a resistive divider with R_f and often disables the oscillator by biasing the circuit out of the linear region of the EXTAL input. This problem can sometimes be overcome by capacitively coupling the oscilloscope with a very small capacitor (1-5 pF) between the oscilloscope probe and the oscillator pin.

It is better to observe the CLKOUT signal, since this does not alter the operation of the oscillator. It may be possible to observe XTAL since it is isolated from the rest of the oscillator by R_s . Observe I_{DD} without the oscilloscope connected and again with it connected. If I_{DD} is unchanged, it is usually safe to assume the oscillator was unaffected. For additional information, see **2.5 Clock Circuitry**.

5.2.4 Problem: System Crashes after Fetching Reset Vector

1. Incorrect reset configuration of boot memory width is causing the address bus to increment by the wrong amount during fetches of the reset vectors. Check DATA0 to make sure that it is being driven to the correct state during reset. If \overline{CSBOOT} is a 16-bit port, drive DATA0 high during reset; if it is an 8-bit port, drive DATA0 low. See **2.1 Using Data Bus Pins to Configure the MCU**.
2. An $\overline{IRQ7}$ interrupt is received during or immediately after reset. The MCU will recognize the interrupt after fetching the reset information and first instruction. In a typical system that is booting out of ROM, stack RAM will not be enabled at this point, and the first bus cycle to write the stack frame will hang the MCU. Make sure that the $\overline{IRQ[7:1]}$ lines are either pulled up through resistors to 5 volts or configure the pins as PORTF I/O lines by pulling DATA9 low during reset. Also, start-up software should enable the stack RAM (by configuring the appropriate chip-select circuits) before enabling the interrupt lines (by writing to the PFPAR register). This problem is likely to be intermittent, as it would only occur if an $\overline{IRQ7}$ interrupt is received in the short time before system initialization. See **2.1 Using Data Bus Pins to Configure the MCU**.
3. An interrupt is received, and the interrupt vectors have not been initialized. Make sure that the interrupt vectors are initialized. See **4.1.3.2 Initializing Exception Vectors Other Than Reset**.
4. The \overline{BR} or \overline{BGACK} pin has floated low and the CPU has relinquished control of the bus. Configure these pins for chip-select operation out of reset by pulling DATA1 high during reset, or put pull-up resistors on these pins.
5. Some of the pins are being powered up before V_{DD} . If the MCU is connected to another system with a separate power supply, use an LVI device to prevent the system with the faster power supply from driving logic one levels before the system with the slower power supply has become operational. If this happens, the driven pins on the device with the slow supply will momentarily have a higher voltage than the V_{DD} pin. This condition can cause the input protection diodes to become momentarily forward biased and cause significant current injection into the device substrate, which will probably improperly charge or discharge some of the internal nodes of the MCU. This action is completely random, and it is impossible to predict what will happen when significant injection occurs. Usually, the MCU will not function at all and will display undefined states. For example, the \overline{RESET} , \overline{HALT} , \overline{BERR} , \overline{BR} and FREEZE signals may be asserted but the device may fail to fetch opcodes. See **2.7 Power Supply**.

5.2.5 Problem: Debug System Cannot Enter BDM

1. $\overline{\text{BKPT}}$ is not held low at the release of $\overline{\text{RESET}}$. Holding $\overline{\text{BKPT}}$ low at the release of $\overline{\text{RESET}}$ enables BDM, and driving it low after reset causes the processor to enter BDM. The debugger should take care of this.
2. The memory is uninitialized, and the processor is trying to access bad addresses. In this case, most debuggers should drive $\overline{\text{BERR}}$ to terminate the bus cycle. If the debugger does not do this, either write valid addresses to the reset vectors or, if this is not possible, manually pulse $\overline{\text{BERR}}$ low to terminate a hung bus cycle.

5.2.6 Problem: The Processor Takes a Spurious Interrupt Exception

1. The interrupt arbitration (IARB) field for the module requesting interrupt service is not a unique, non-zero value. Each internal module has its own IARB field. External interrupts use the IARB field in the SIMCR interrupts.
2. There are noise spikes on an $\overline{\text{IRQ}}$ line. Use pull-up resistors on the $\overline{\text{IRQ}}$ lines.
3. A square wave is used to generate external interrupts, and the source of the interrupt is going away before the interrupt is acknowledged.
4. The program code is disabling an internal module or is arbitrarily clearing interrupt enable bits for an internal module before the interrupt is acknowledged. Instead of arbitrarily clearing the enable bits, first mask out the interrupt level by writing to the IPL field in the CPU status register. For example, if a level 3 interrupt is to be masked, set the IPL field to three or higher. Then, disable the enable bit for the specific interrupt.
5. An internal module is initialized improperly in such a way that the module cannot respond with an internal $\overline{\text{DSACK}}$ even when that module is the one asserting the interrupt.
6. The $\overline{\text{IACK}}$ cycle is terminated by $\overline{\text{BERR}}$ instead of $\overline{\text{DSACK}}$ or $\overline{\text{AVEC}}$. The assertion of $\overline{\text{BERR}}$ causes the spurious interrupt vector (vector number 24) to be taken. A spurious interrupt will be taken in the following three situations:
 - A. The CPU recognizes the occurrence of a valid interrupt request and begins the IACK cycle. If none of the modules enter arbitration by asserting an IARB field value, the spurious interrupt monitor asserts $\overline{\text{BERR}}$ internally.
 - B. After arbitration, the interrupt source that wins arbitration does not terminate the IACK cycle with $\overline{\text{DSACK}}$ or $\overline{\text{AVEC}}$. In this case, the bus monitor asserts the internal $\overline{\text{BERR}}$ signal.
 - C. An external device terminates the IACK cycle by asserting $\overline{\text{BERR}}$.

An interrupt request signal *must* remain asserted from the time it first occurs until the end of the IACK cycle. The most common cause of spurious interrupts is a periodic signal, such as a square wave, connected to an external interrupt request line. Other signals, such as the output of a shaft decoder, will also cause spurious interrupts. Latch periodic or intermittent signals by means of an external circuit, and clear the latch in the interrupt service routine.

5.2.7 Problem: The Processor Asserts $\overline{\text{HALT}}$ and Halts

A double bus fault has occurred, and the halt monitor (previously called the double bus fault monitor) is not enabled. A double bus fault can occur under the following conditions.

1. When bus error exception processing begins, and a second bus error is detected before the first instruction of the first exception handler is executed.
2. When one or more bus errors occur before the first instruction after a reset is executed.
3. When a bus error occurs while the CPU is loading information from a bus error stack frame during execution of a return from exception (RTE) instruction.

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After the double bus fault occurs, the MCU drives the $\overline{\text{HALT}}$ line low and can only be restarted by a reset. When the $\overline{\text{HALT}}$ line is driven low internally, the double bus fault monitor will immediately cause a reset if it is enabled. If the double bus fault monitor has been disabled by clearing the HME bit in the system protection control register (SYPCR), the MCU will remain halted indefinitely and must be reset externally.

5.2.8 Problem: A Chip-Select Generates the Wrong Number of Wait States

1. Either $\overline{\text{DSACK1}}$ or $\overline{\text{DSACK0}}$ has floated low. These signals should be tied high via a pull-up resistor or be configured as I/O pins. The $\overline{\text{DSACK}}$ pins, along with other bus control signals, are configured as I/O pins by driving DATA8 low during reset or by programming the appropriate CS-PAR bits.
2. Multiple chip-selects with different wait states are responding to the same address (it does not matter whether the chip-select pins are connected to anything). Whether or not multiple chip-selects respond to the same address is determined by both the base address and the block size in the associated chip-select base address register (CSBAR).
3. The MCU sees only base addresses that lie on a word boundary of the block size. It will interpret each base address as an address that is on a word boundary. This will cause an incorrectly programmed chip-select circuit to match on an unexpected address. An example of how to determine if chip-select circuits are programmed correctly is shown below.
 - A. On a sheet of paper, make a table with four columns as shown in **Table 8**. Initialize the base address and option registers, then look at all of the base address and option registers. Fill in the appropriate cell in the table with the value in the corresponding option register and base address register. In addition, fill in the BLKSZ cell with the block size indicated by the last three bits of the base address register. **Table 9** shows block size values.
 - B. Compare the base address register values to see if any overlap. In addition to checking the actual values in the registers, check the block sizes and thus the number of address lines compared. Since the MCU does not look at all 24 address lines when it compares for a match, two chip-select circuits can respond to the same base address, even though the base address registers contain different values.

Table 8 Sample Chip-Select Values

CS	CSBARx	CSORx	BLKSZ
$\overline{\text{CSBOOT}}$	\$0003	\$68B0	64K
$\overline{\text{CS0}}$	\$0504	\$58FE	128K
$\overline{\text{CS1}}$	\$F800	\$5830	16K
.	.	.	.
.	.	.	.
$\overline{\text{CS10}}$	\$0400	\$4F3E	2K

Table 9 Block Size Encodings for Chip-Selects

BLKSZ[2:0]	Block Size	Address Lines Compared
000	2 Kbyte	ADDR[23:11]
001	8 Kbyte	ADDR[23:13]
010	16 Kbyte	ADDR[23:14]
011	64 Kbyte	ADDR[23:16]
100	128 Kbyte	ADDR[23:17]
101	256 Kbyte	ADDR[23:18]

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Table 9 Block Size Encodings for Chip-Selects

BLKSZ[2:0]	Block Size	Address Lines Compared
110	512 Kbyte	ADDR[23:19]
111	1 Mbyte	ADDR[23:20]

In **Table 8** the addresses for CS0 and CS10 conflict. Both will respond to the address \$40000. CS0 is programmed to start at \$50000; however, it is programmed incorrectly. It does not lie on an even boundary of 128 Kbytes (remember that 1 Kbyte = 1024 bytes). As shown in **Table 9**, only address lines 23 through 17 are compared for a block size of 128 Kbytes. The address decoding process works as follows.

CSBAR0: \$0504 = base address of \$50000 and block size of 128K.

$$\begin{array}{r}
 \\
 23 \ 20 \ 19 \ 16 \ 15 \ 12 \ 11 \ 8 \ 7 \ 4 \ 3 \ 0 \\
 \$5000 =
 \end{array}$$

For a 128 Kbyte block size, address lines 16–0 are decoded as zero. As a result, bits [19:16] are read as a four instead of a five, and $\overline{CS0}$ responds to the address space starting at location \$40000. However, $\overline{CS10}$ is also programmed to respond to the address space starting at location \$40000. It is acceptable for two chip-select circuits to respond to the same address space; however, in this case, the option registers are programmed for a different number of wait states. As a result, the first termination signal seen will be from $\overline{CS0}$ after three wait states on any read or write access, possibly before the external device is ready to respond, especially if it was meant to have $\overline{CS10}$ terminate the cycle after 12 wait states.

To correct the problem, the values in CSBAR0 and/or CSBAR10 must be changed. If the value in CSBAR0 is changed to \$0404, and the value in CSBAR10 is changed to a base address that does not overlap, such as \$0300, then \$40000 is an acceptable base address for CS0, since it is an exact multiple of 128 Kbytes. That is:

$$1K = \$400$$

$$128K = \$20000$$

$$\$40000 / \$20000 = 2 = \text{an integer}$$

Therefore, \$40000 is on a 128 Kbyte boundary

5.2.9 Problem: A Chip-Select Does Not Assert

Ensure that a valid base address is written to the chip-select base address register. Because the CPU16 does not recognize addresses \$80000 to \$F7FFFF, base address register values \$0800 to \$F7FF are invalid.

5.3 Problem: ADC Results are Inaccurate

1. Ensure that V_{DDA} and V_{SSA} are as noise-free as possible and are as isolated from the digital power supply as possible.
2. Ensure that V_{RH} and V_{RL} are within the voltage limits specified by V_{DDA} and V_{SSA} and that they are as noise-free and clean as possible.
3. Ensure that the analog inputs to AD[0:7] are within the voltage limits specified by V_{RH} and V_{RL} and that they are as noise-free and clean as possible. Also, ensure that the inputs are low-leakage/low impedance. Ensure that the input current does not exceed the disruptive input current specification for the device.

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Refer to **4.6 Configuring the Analog-to-Digital Converter** earlier in this tutorial and Chapter 6 in the *ADC Reference Manual (ADCRM/AD)*.

6 Sources of Information

6.1 Technical Literature

All Freescale literature can be ordered by mail from Freescale Literature Distribution Centers (shown on the back page of this publication) or through local sales offices. For U.S. and European literature orders, call (800) 441-2447. Freescale publication BR1116/D *Advanced Microcontroller Technical Literature*, includes a complete listing of literature, sales offices, distributors, and an order form.

6.1.1 User's Manual

MC68HC16Z1 User's Manual (MC68HC16Z1UM/AD)

6.1.2 Reference Manuals

M683HC16 Family CPU16 Central Processor Unit Reference Manual (CPU16RM/AD).

Modular Microcontroller Family Analog-to-Digital Converter Reference Manual (ADCRM/AD).

Modular Microcontroller Family Queued Serial Module Reference Manual (QSMRM/AD).

Modular Microcontroller General-Purpose Timer Reference Manual (GPTRM/AD).

Modular Microcontroller Family System Integration Module Reference Manual (SIMRM/AD).

6.1.3 Application Notes

AN437/D	<i>Using the MC68332 Periodic Interrupt Timer</i>
AN461/D	<i>An Introduction to the HC16 for HC11 Users</i>
AN1050/D	<i>Designing for Electromagnetic Compatibility with HCMOS Microcontrollers</i>
AN1051/D	<i>Transmission Line Effects in PCB Applications</i>
AN1058/D	<i>Reducing A/D Errors in MCU Applications</i>
AN1062/D	<i>Using the QSPI for Analog Data Acquisition</i>
AN1213/D	<i>16-Bit DSP Servo Control with the HC16Z1</i>
AN1230/D	<i>A BDM Driver Package for Modular Microcontrollers</i>
AN1233/D	<i>Using the M68HC16 DSP to Build an Audio Frequency Analyzer</i>
AN1249/D	<i>Brushed DC Motor Control Using the MC68HC16Z1</i>
AN1254/D	<i>M68HC16 Audio Tone Generation</i>
AN1310/D	<i>Using the MC68HC16Z1 Microcontroller for AC Induction Motor Control</i>
M68HC16PN01/D	<i>Transporting M68HC11 code to M68HC16 devices</i>

6.1.4 Development Tools and Software

Freescale Microcontroller Development Tools Directory (MCUDEVTLDIR/D).

6.1.5 Books

Programming Microcontrollers in C (TB328)

6.2 Freeware Data Systems

The Freescale Freeware BBS can be accessed by modem at phone number (512) 891-3733. Freeware can be accessed via internet at freeware.aus.sps.mot.com. For World Wide Web access, use <http://>

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freeware.aus.sps.mot.com/. The Freeware system contains a wealth of information concerning Freescale MCUs and downloadable software.

6.2.1 Application Snapshots

Application snapshots provide brief discussions of commonly-encountered problems and technical issues concerning MCUs. Snapshots are available on the Freeware system — access the Tech_Notes area to see a list of topics and download snapshots. The system provides instructions concerning navigation and downloading files.

6.3 Other Sources

“EDN Magazine’s Designer’s Guide to Electromagnetic Compatibility.” Call (800) 523-9654 for a reprint of the article.

EITD Electronic Industry Telephone Directory. Lists phone numbers, addresses, and fax numbers of about 30,000 sources for electronics products and services. Call (800) 888-5900 or (216) 425-9000.

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